

FIG. 1A

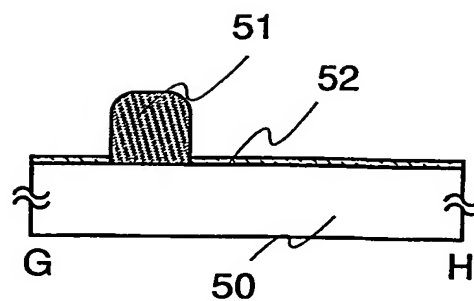


FIG. 1E

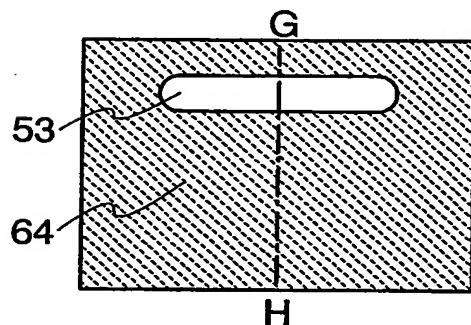


FIG. 1B

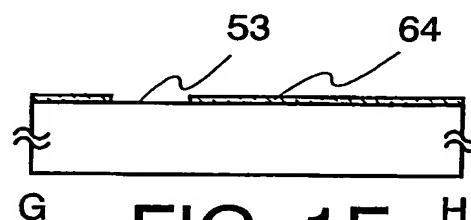


FIG. 1F

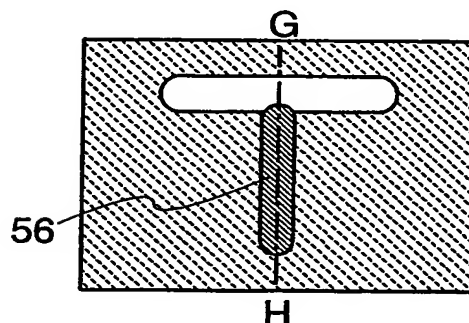


FIG. 1C

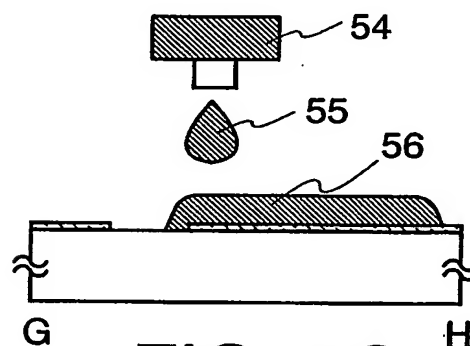


FIG. 1G

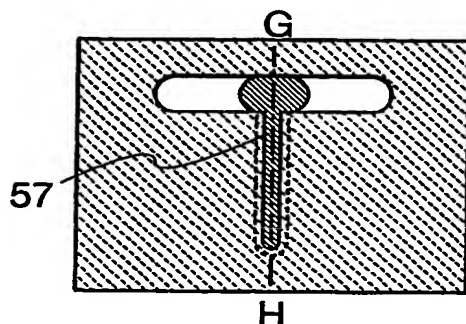


FIG. 1D

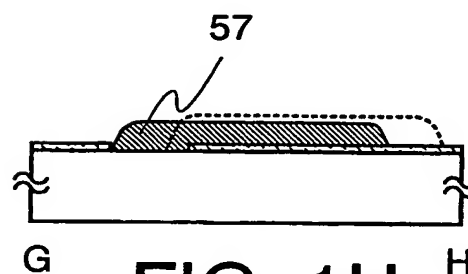


FIG. 1H

BEST AVAILABLE COPY

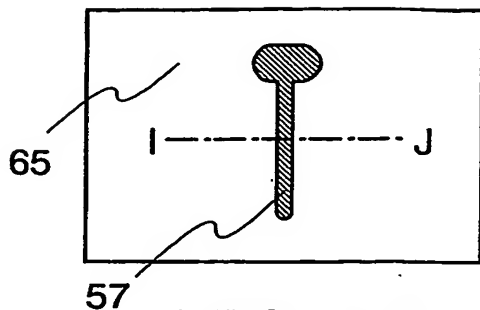


FIG. 2A

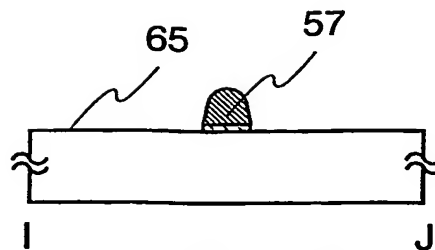


FIG. 2E

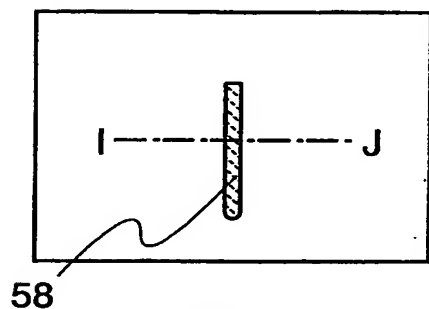


FIG. 2B

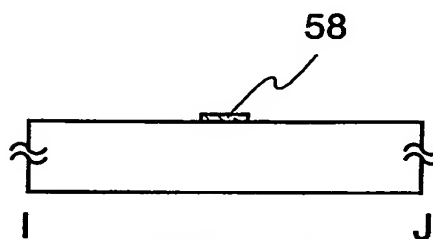


FIG. 2F

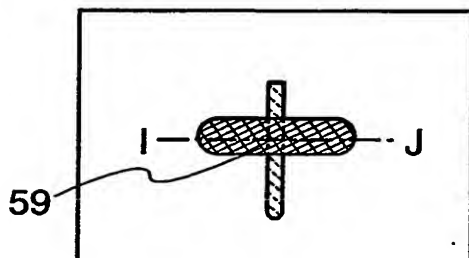


FIG. 2C

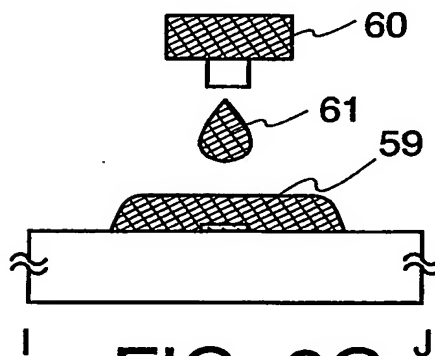


FIG. 2G

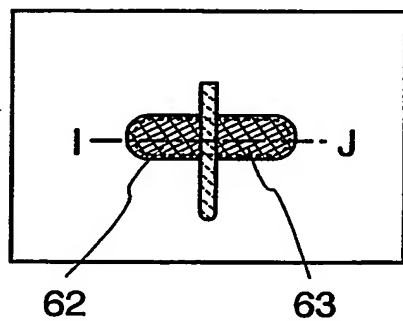


FIG. 2D

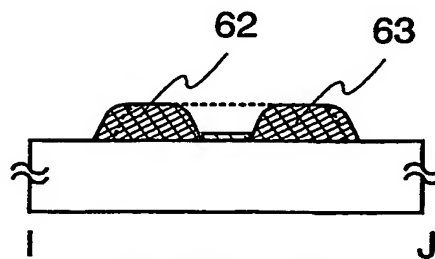


FIG. 2H

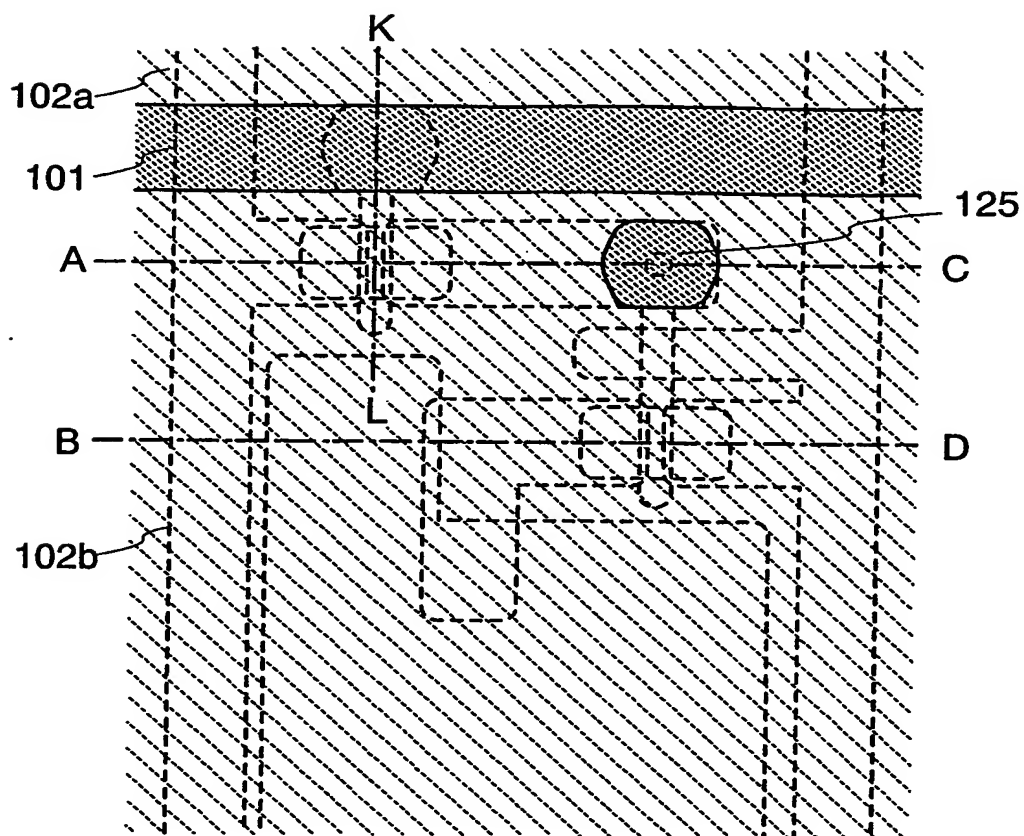


FIG. 3

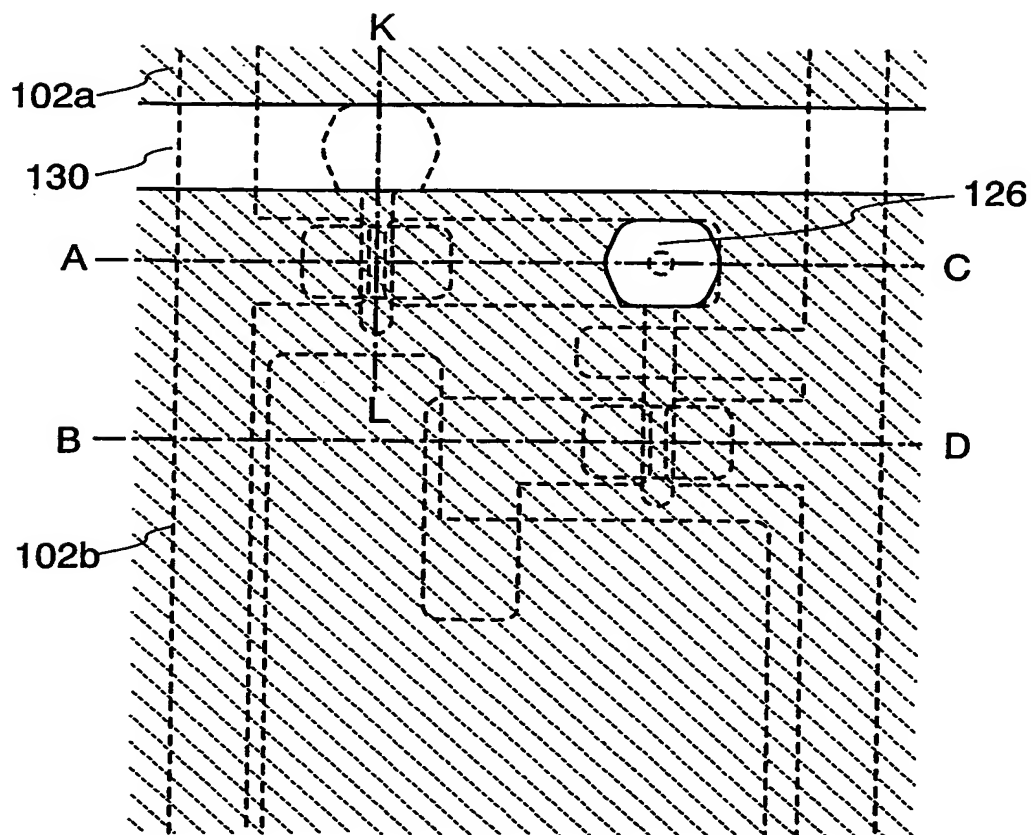


FIG. 4

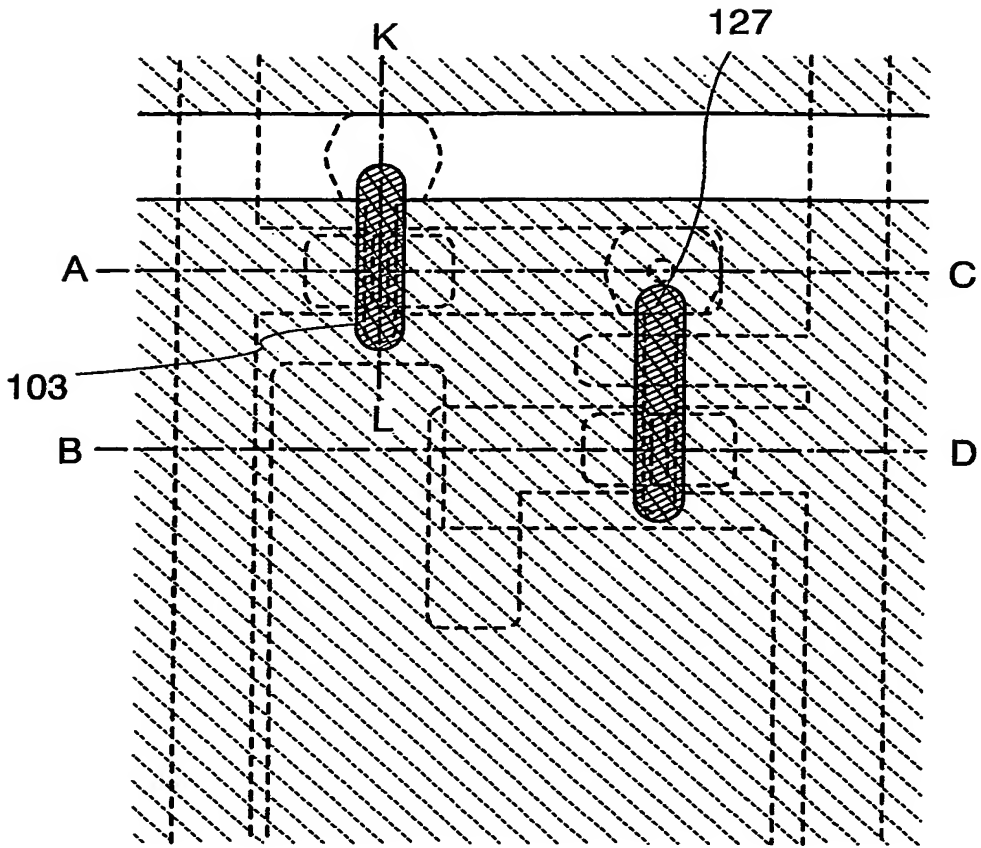


FIG. 5

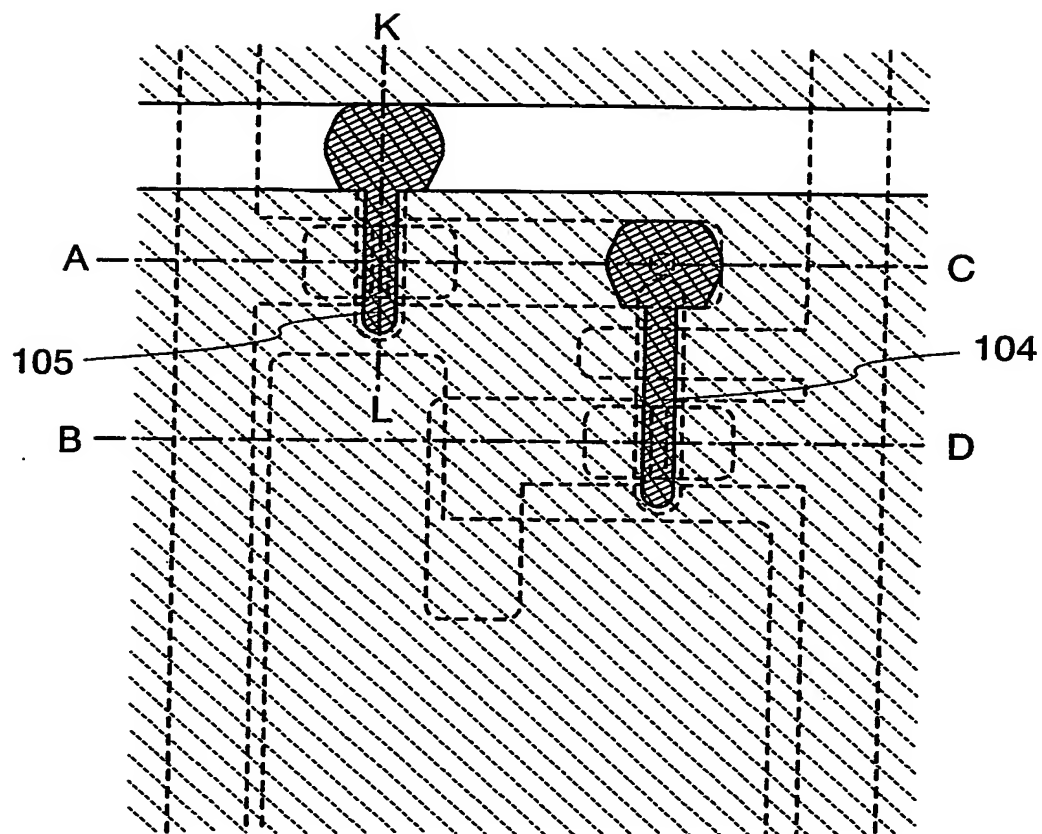


FIG. 6

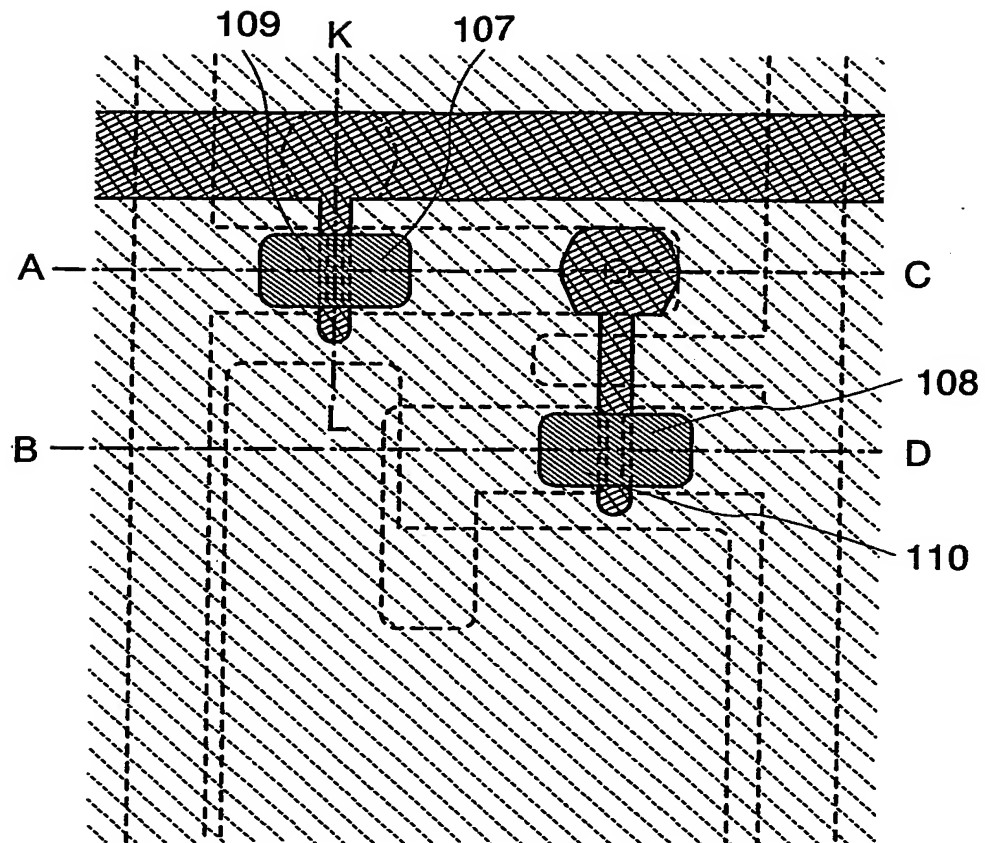


FIG. 8

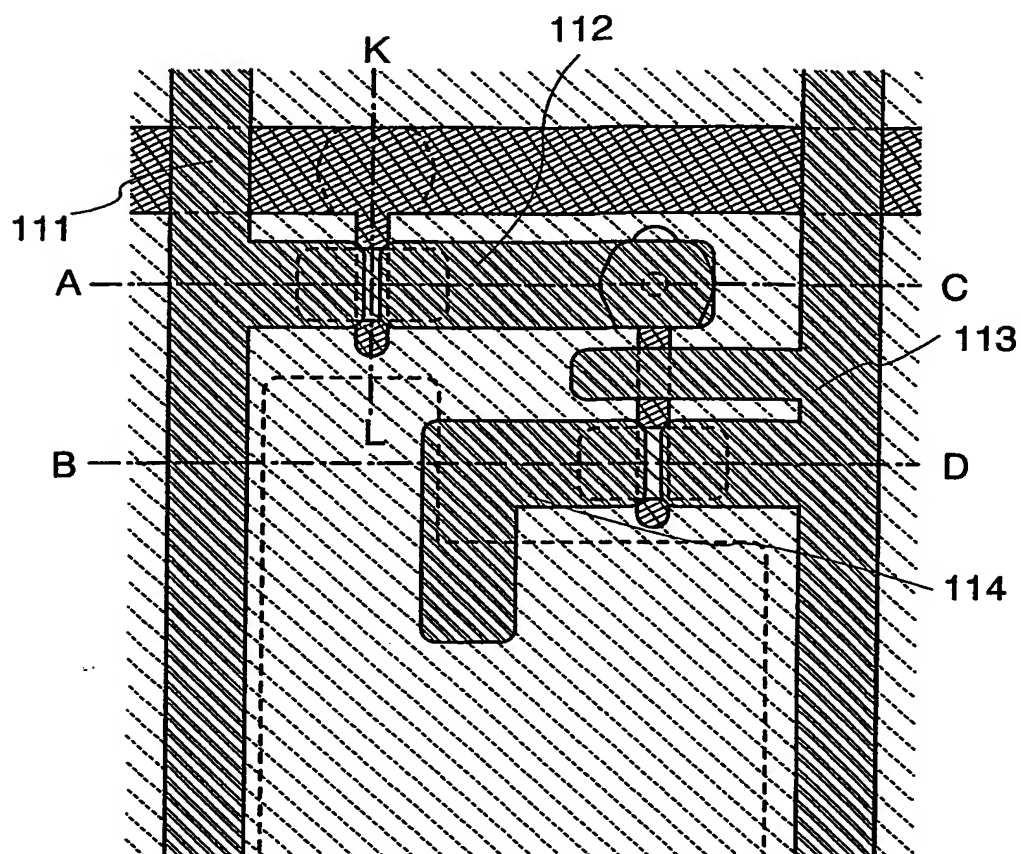


FIG. 9

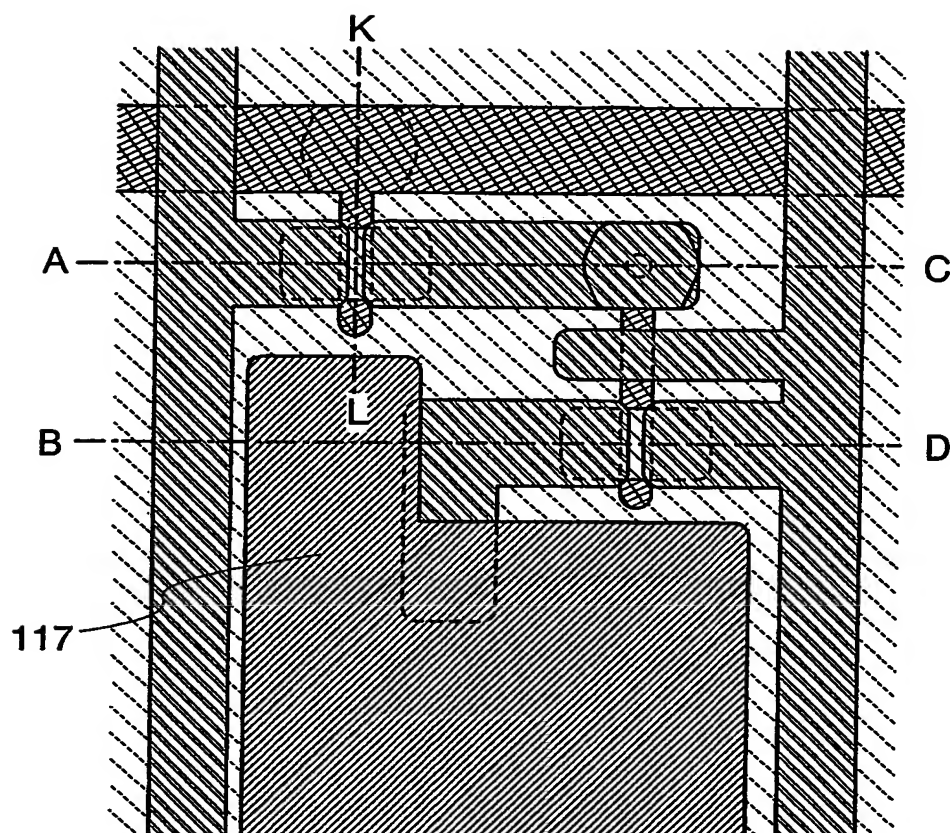


FIG. 10

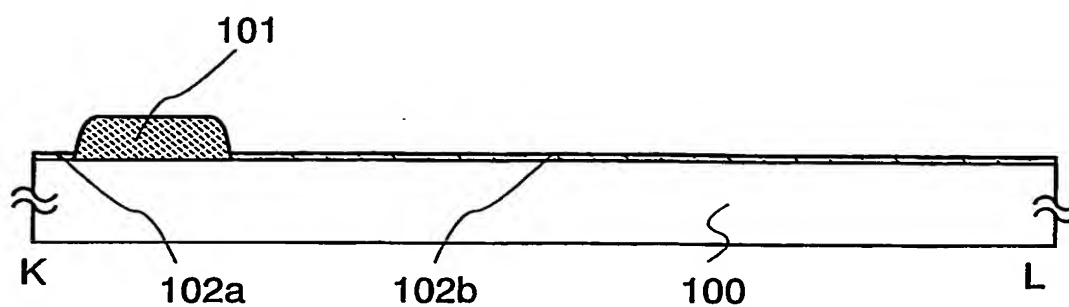


FIG. 11A

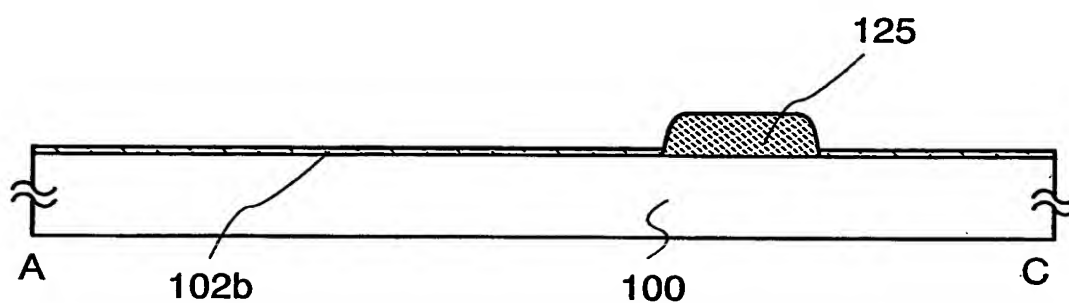


FIG. 11B

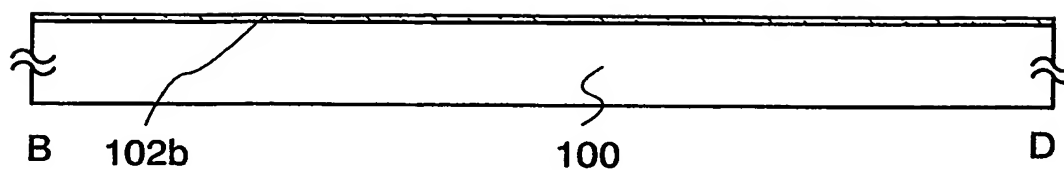


FIG. 11C

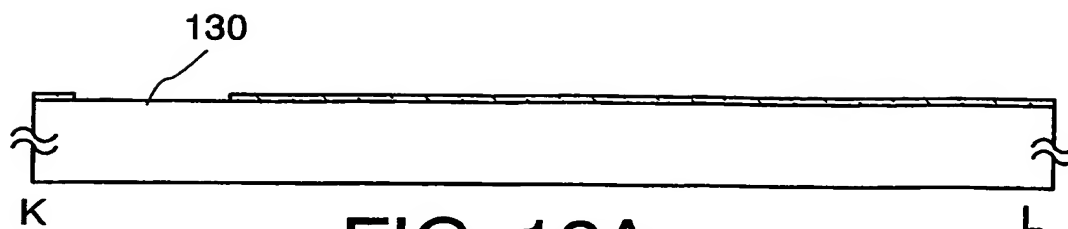


FIG. 12A

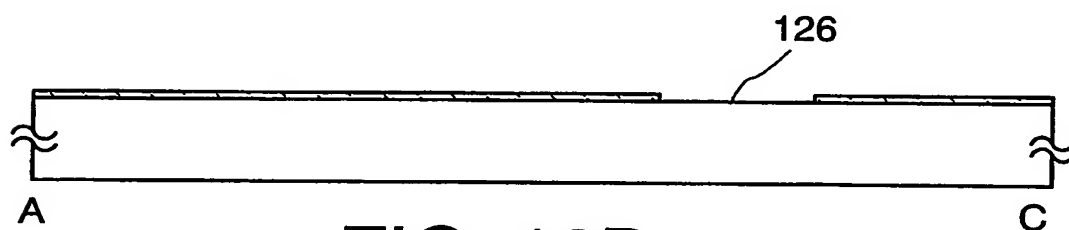


FIG. 12B

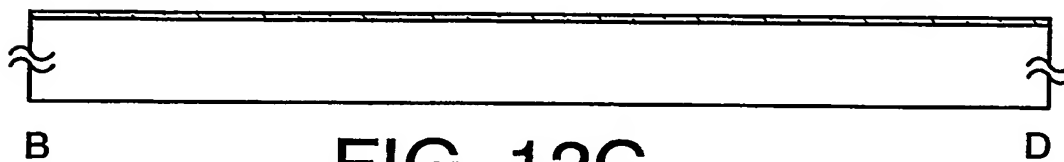


FIG. 12C

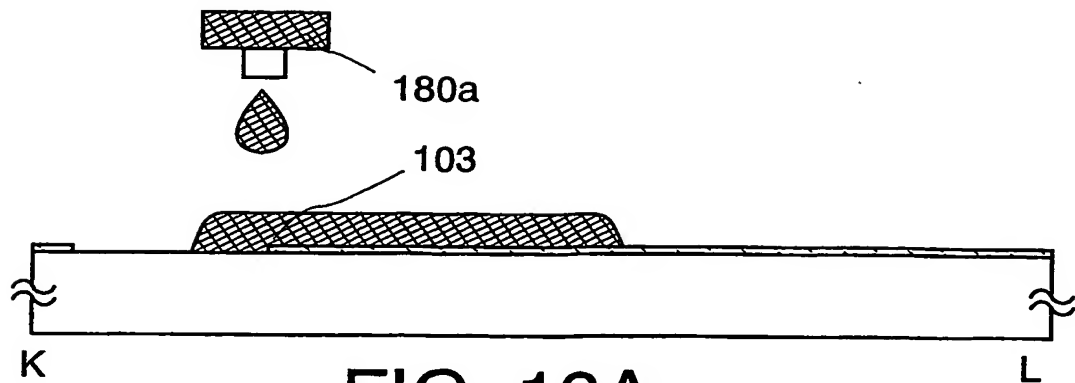


FIG. 13A

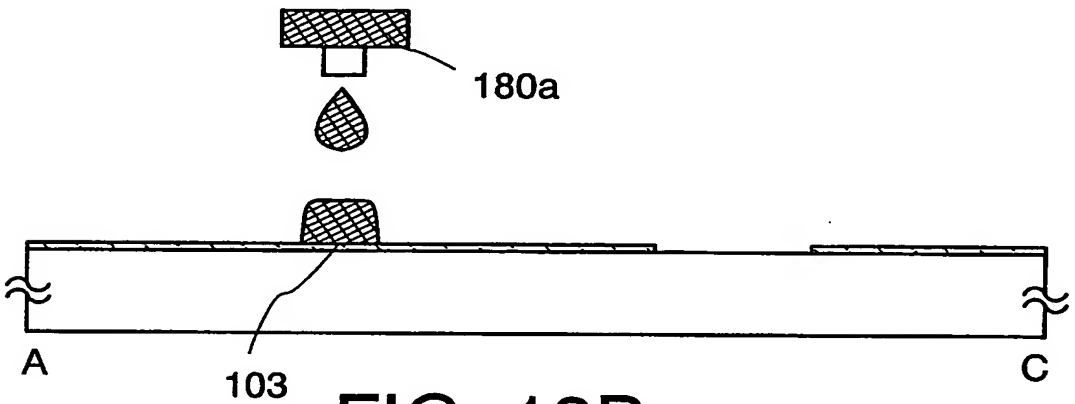


FIG. 13B

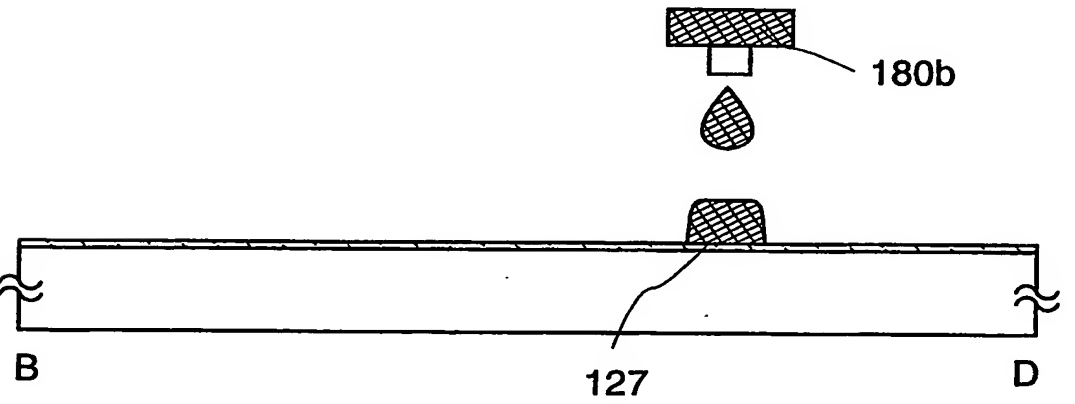


FIG. 13C

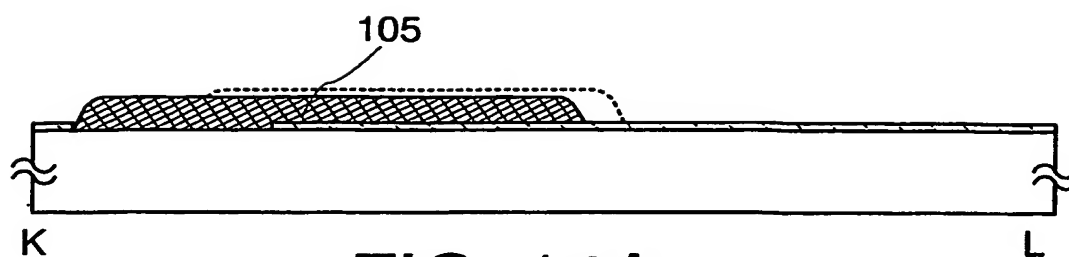


FIG. 14A

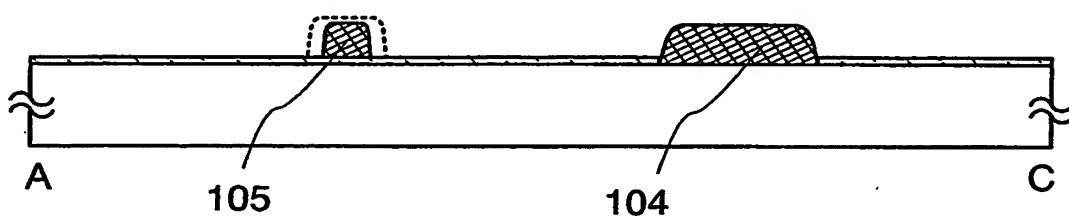


FIG. 14B

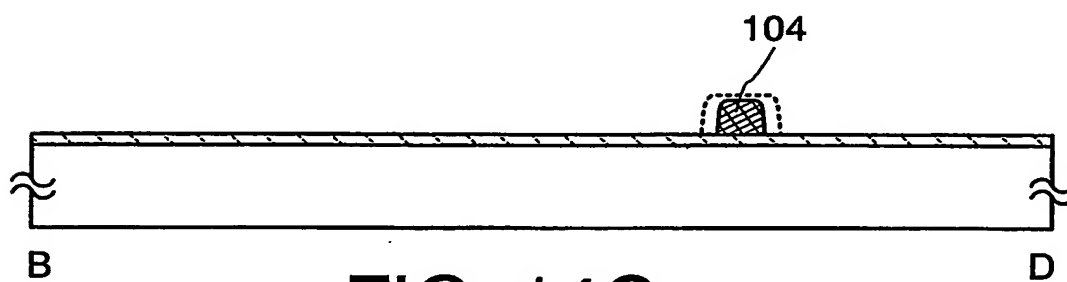


FIG. 14C

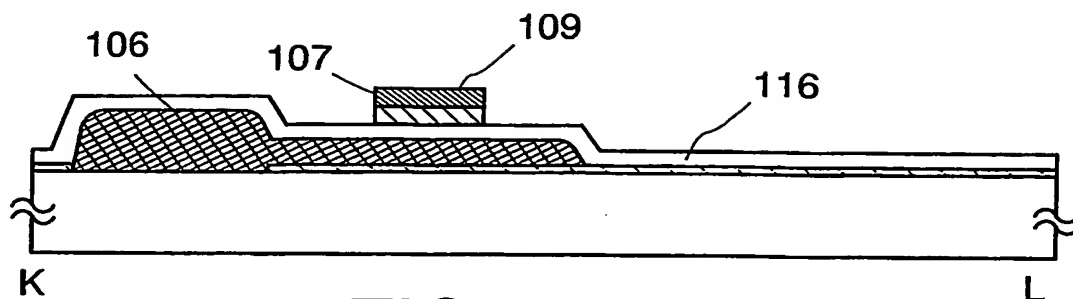


FIG. 15A

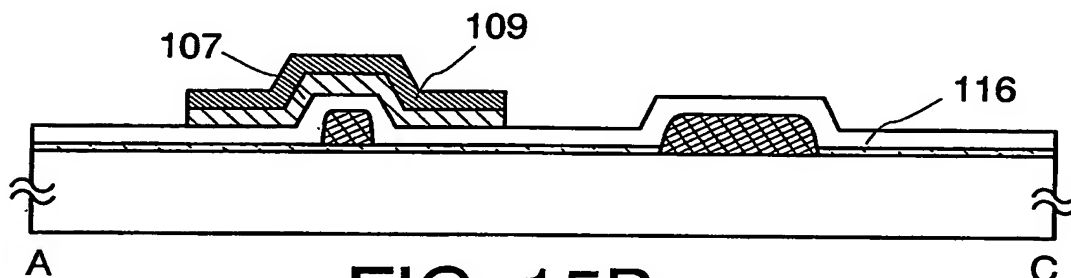


FIG. 15B

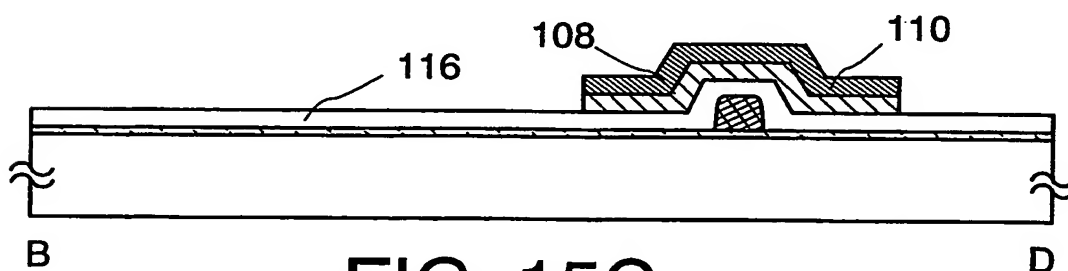


FIG. 15C

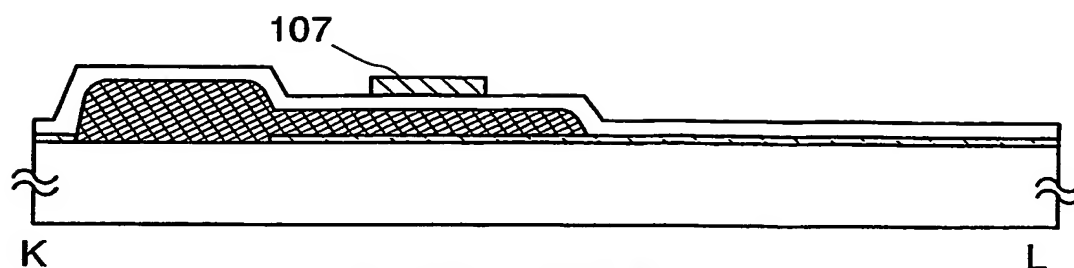


FIG. 16A

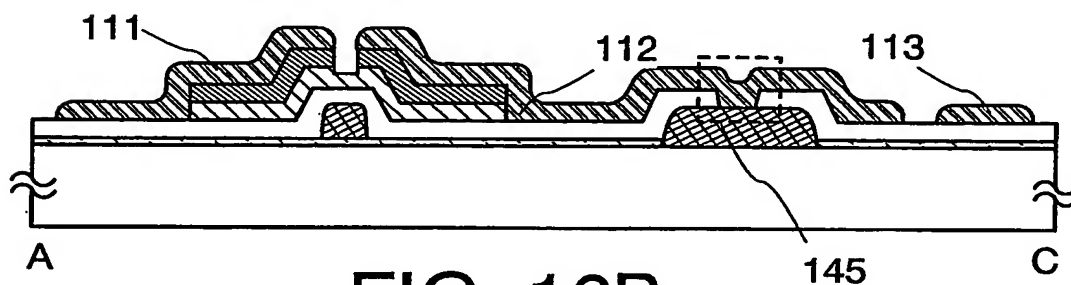


FIG. 16B

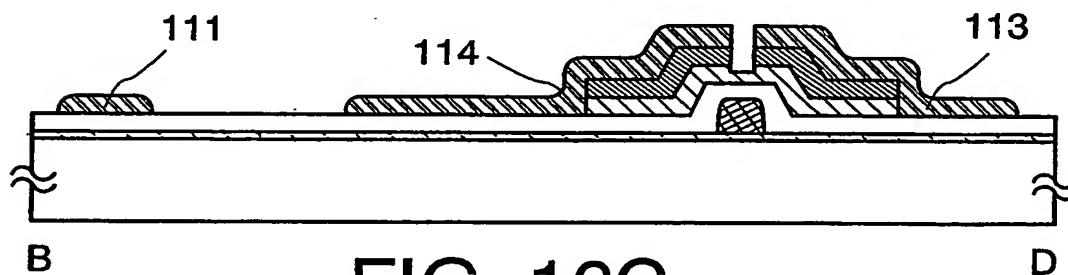


FIG. 16C

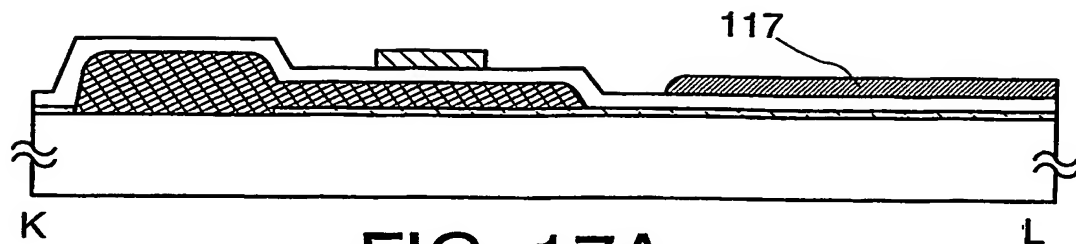


FIG. 17A

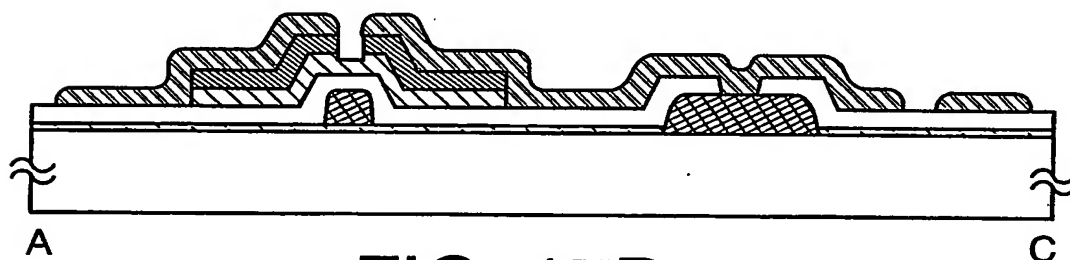


FIG. 17B

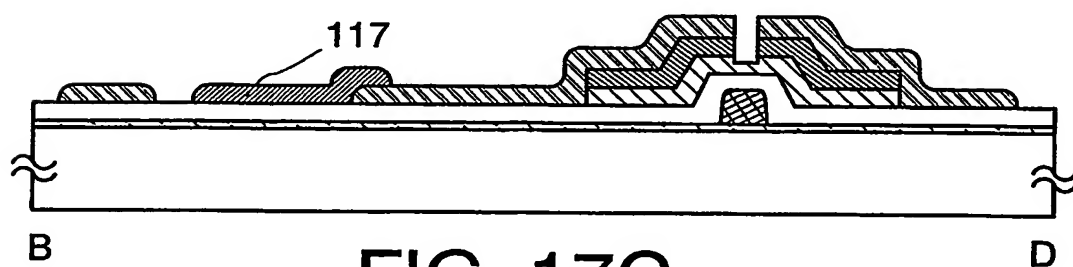


FIG. 17C

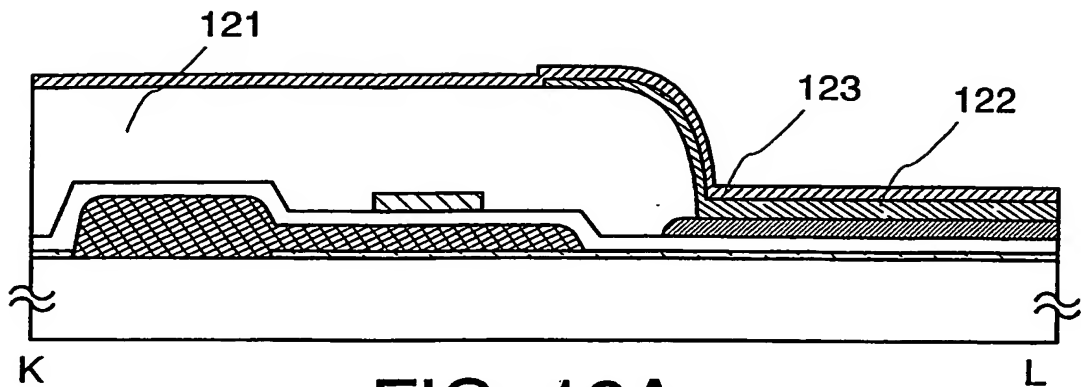


FIG. 18A

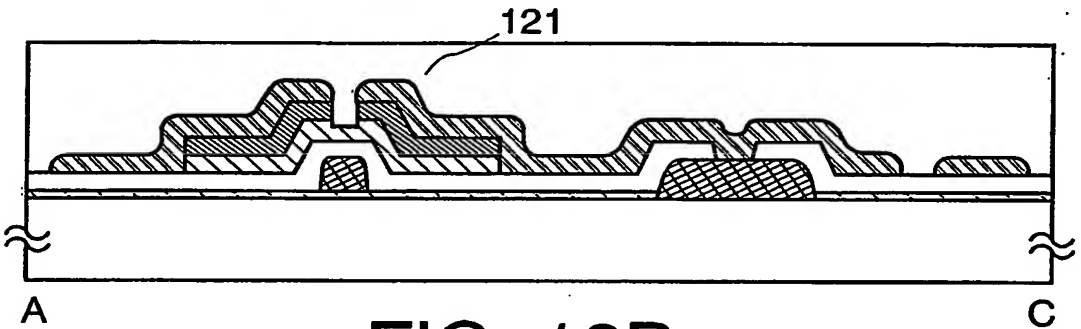


FIG. 18B

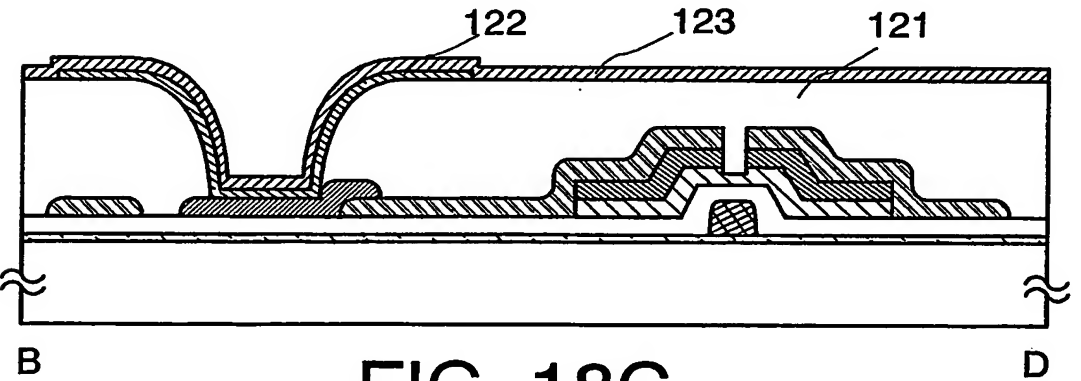


FIG. 18C

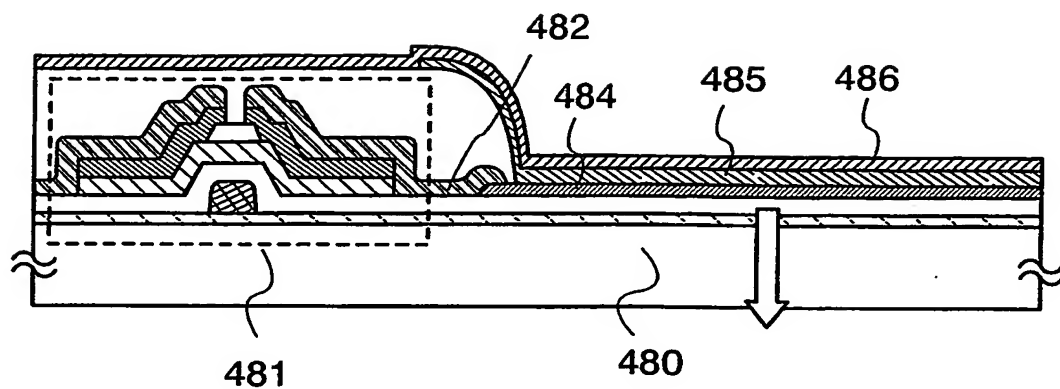


FIG. 19A

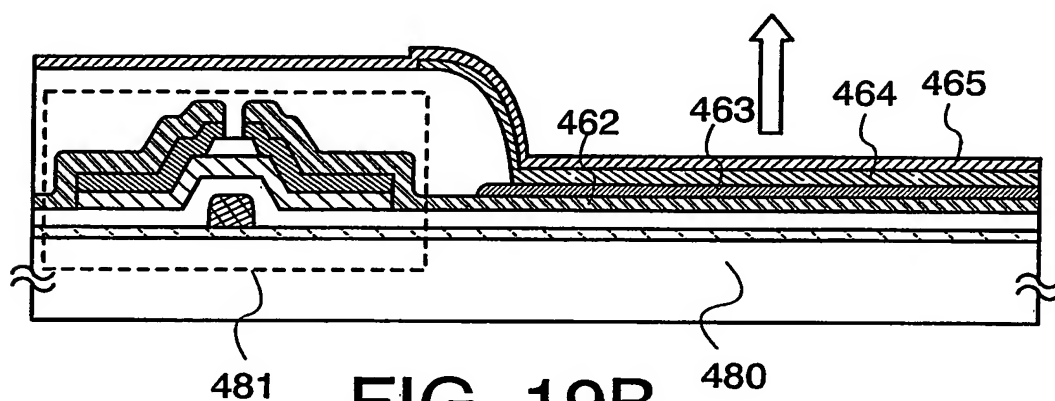


FIG. 19B

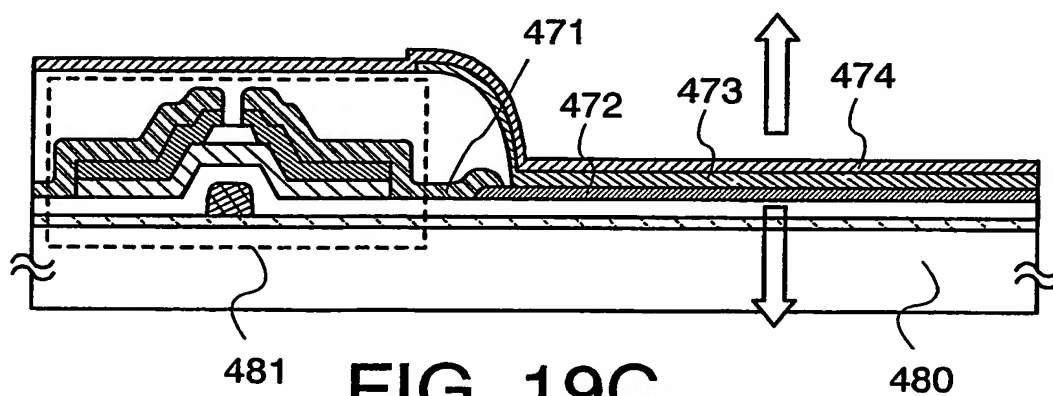


FIG. 19C

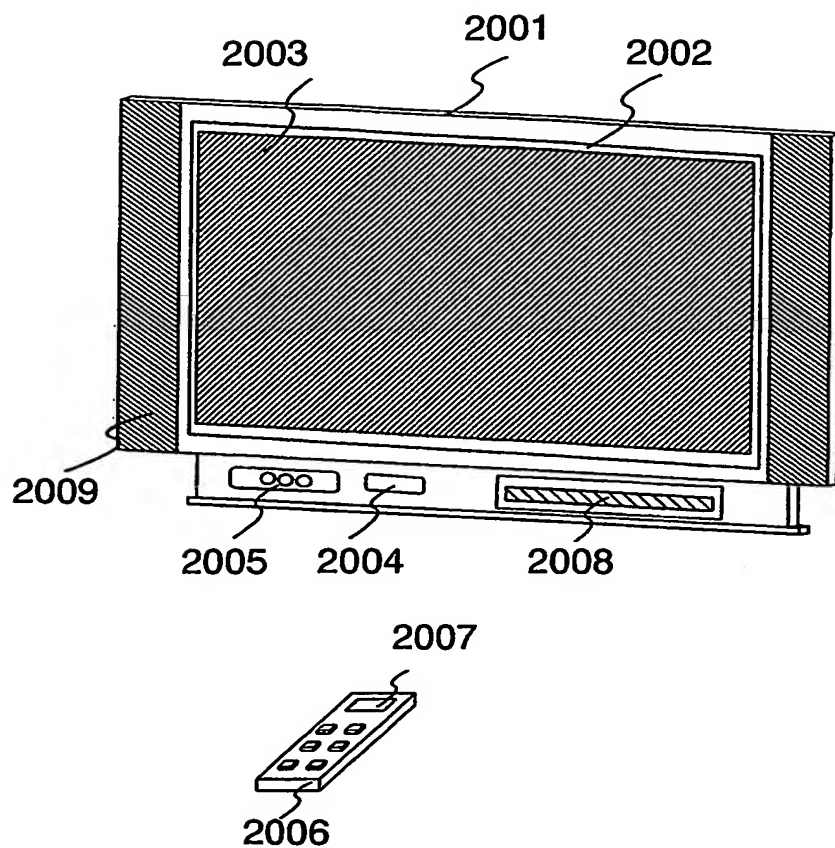


FIG. 20

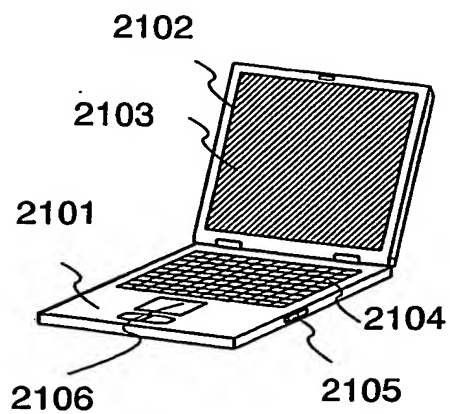


FIG. 21A

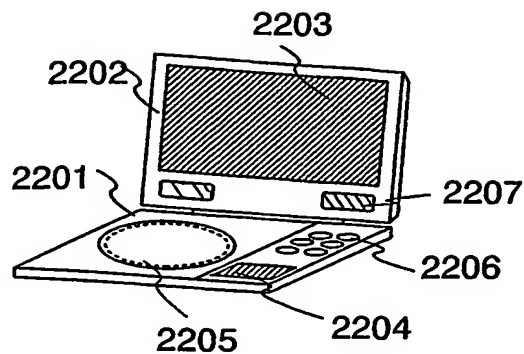


FIG. 21B

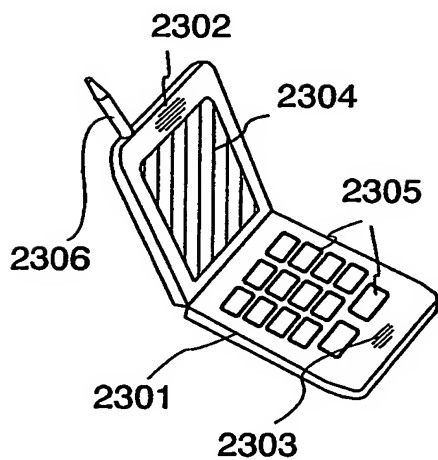


FIG. 21C

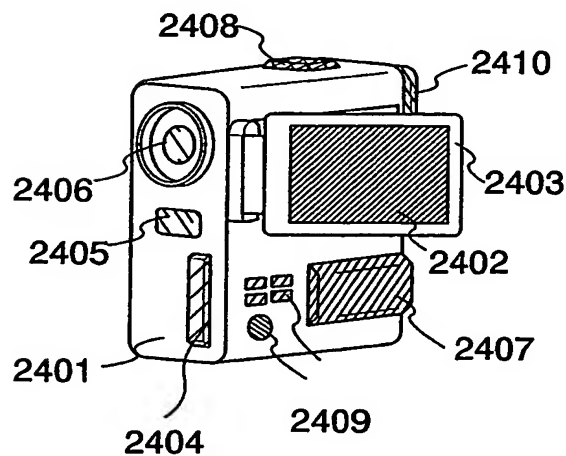


FIG. 21D

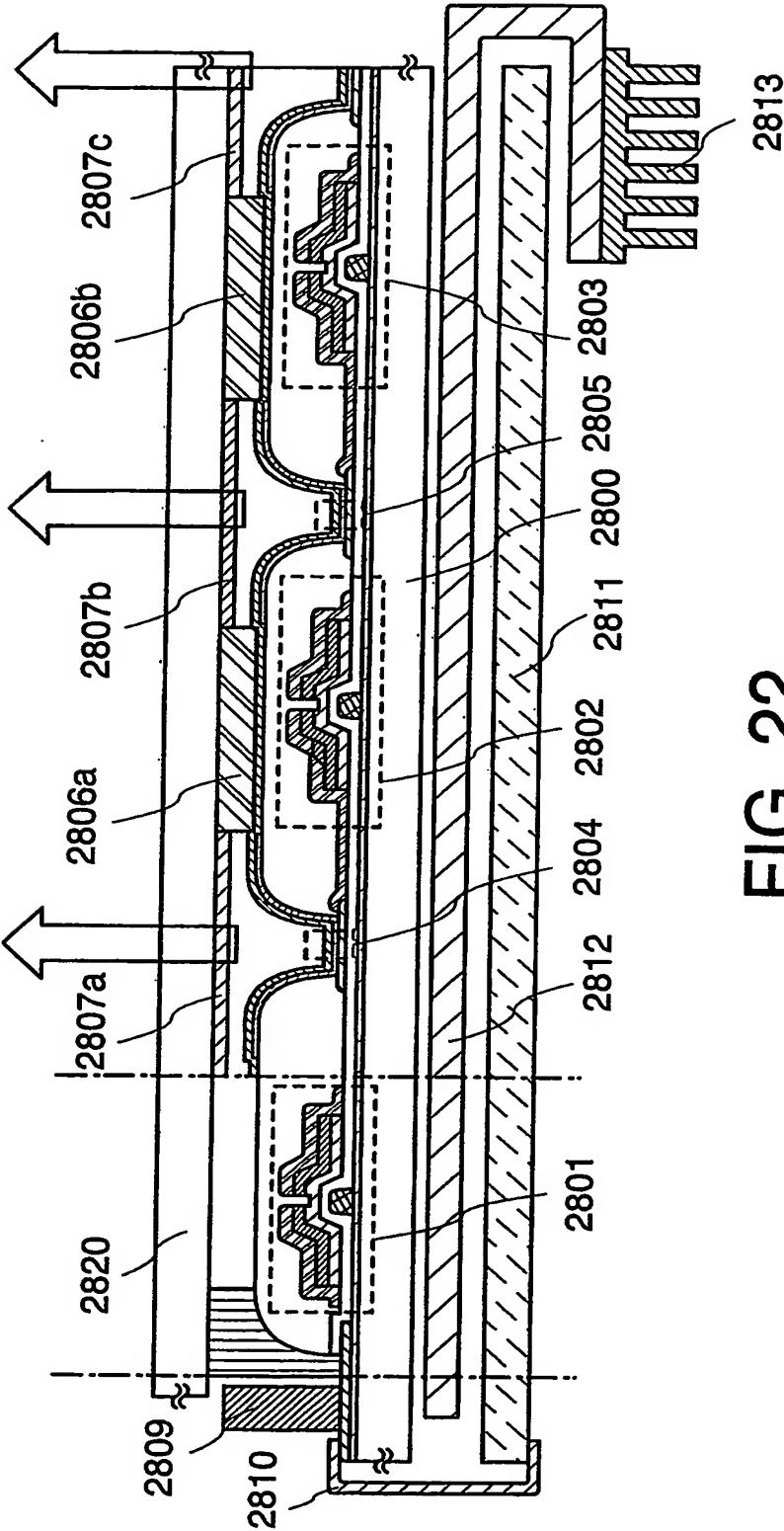


FIG. 22

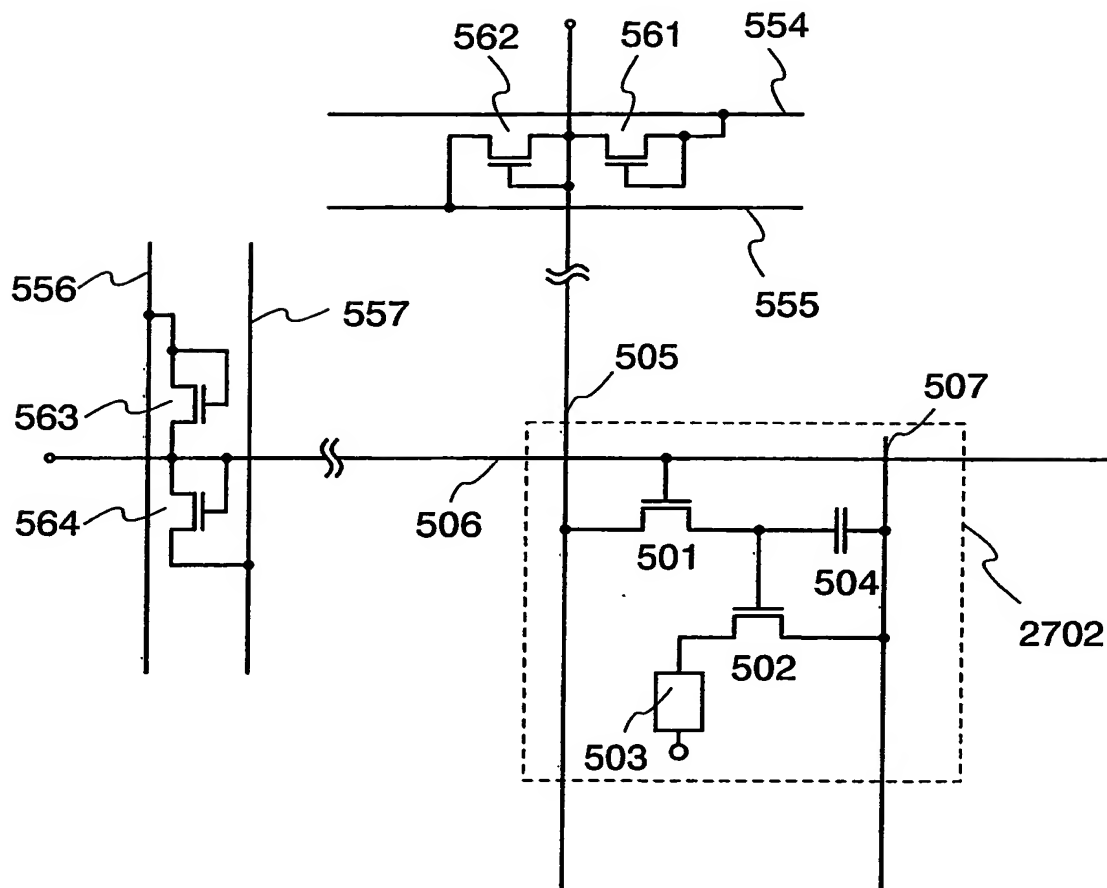


FIG. 23

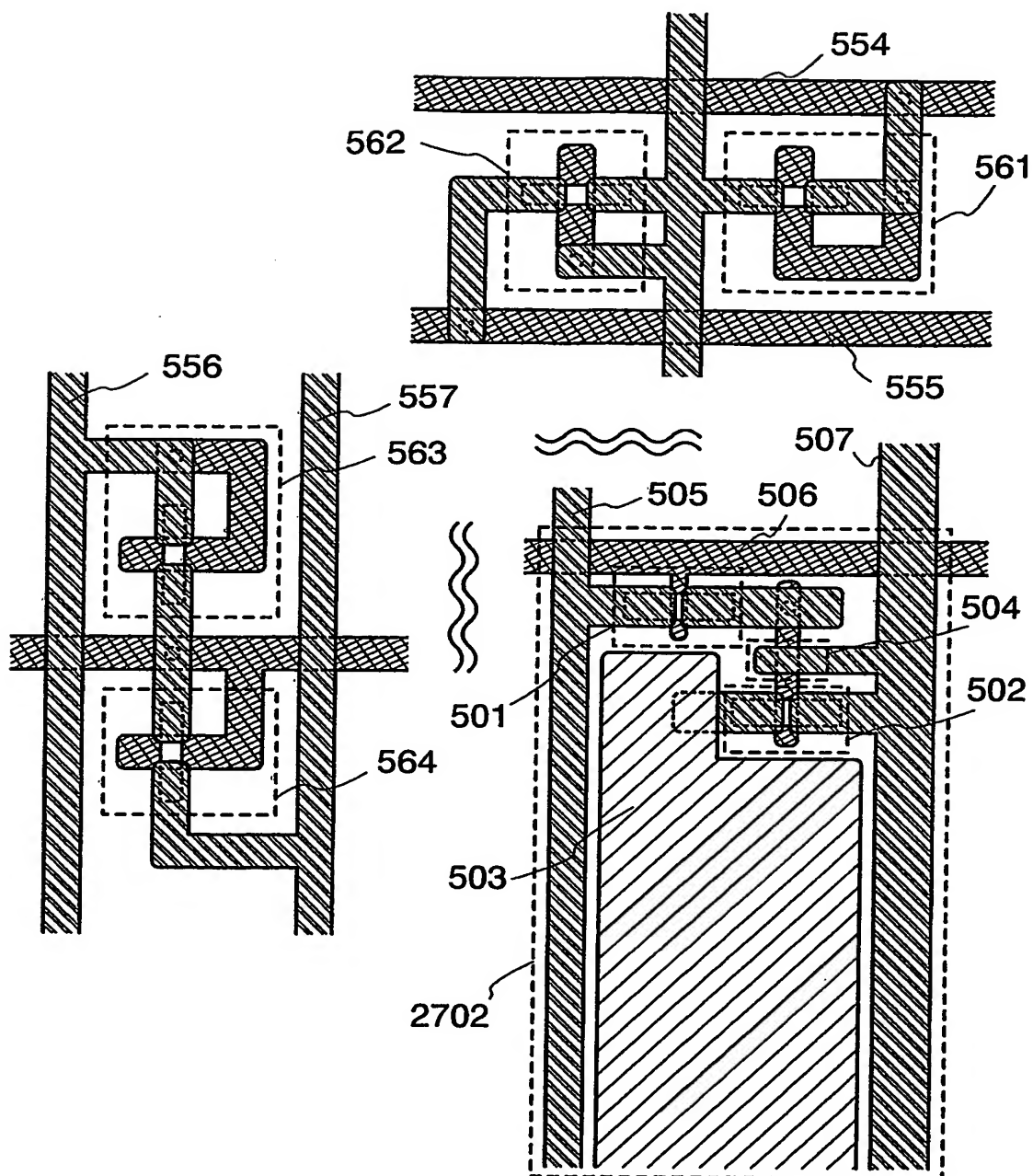


FIG. 24

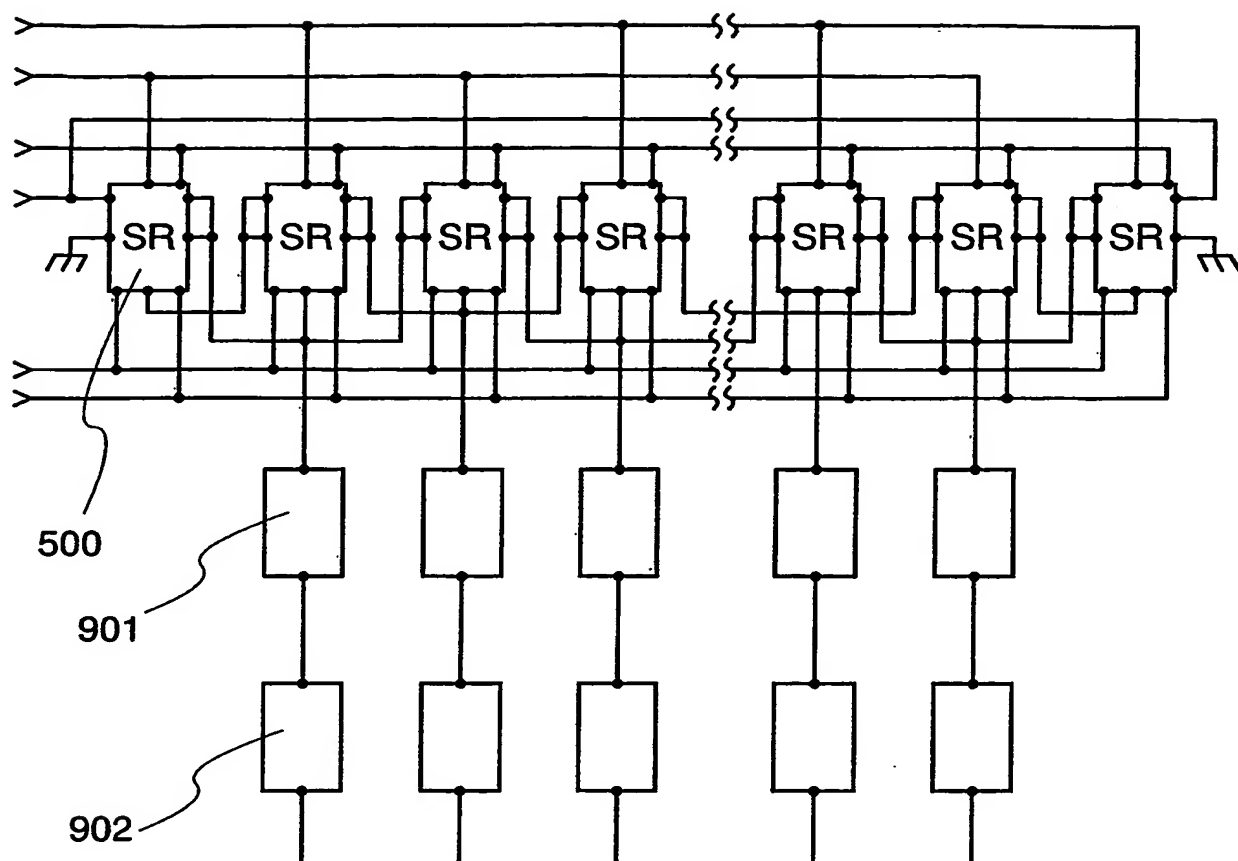


FIG. 25

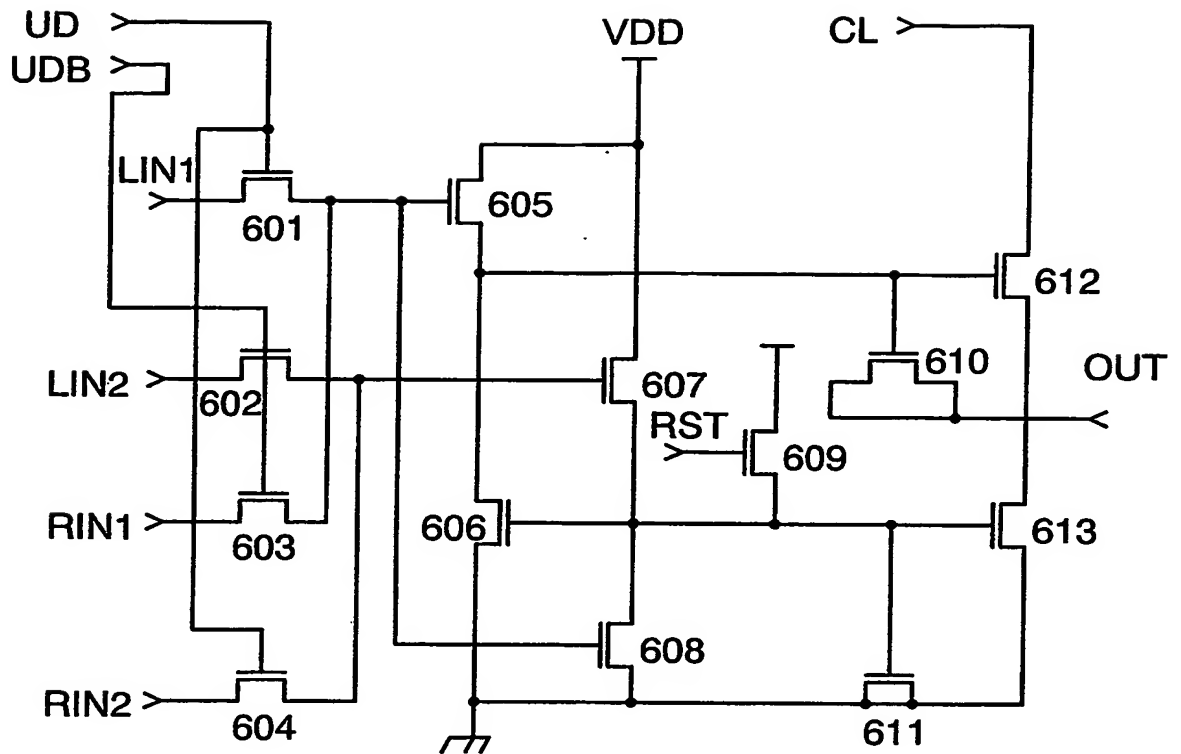


FIG. 26

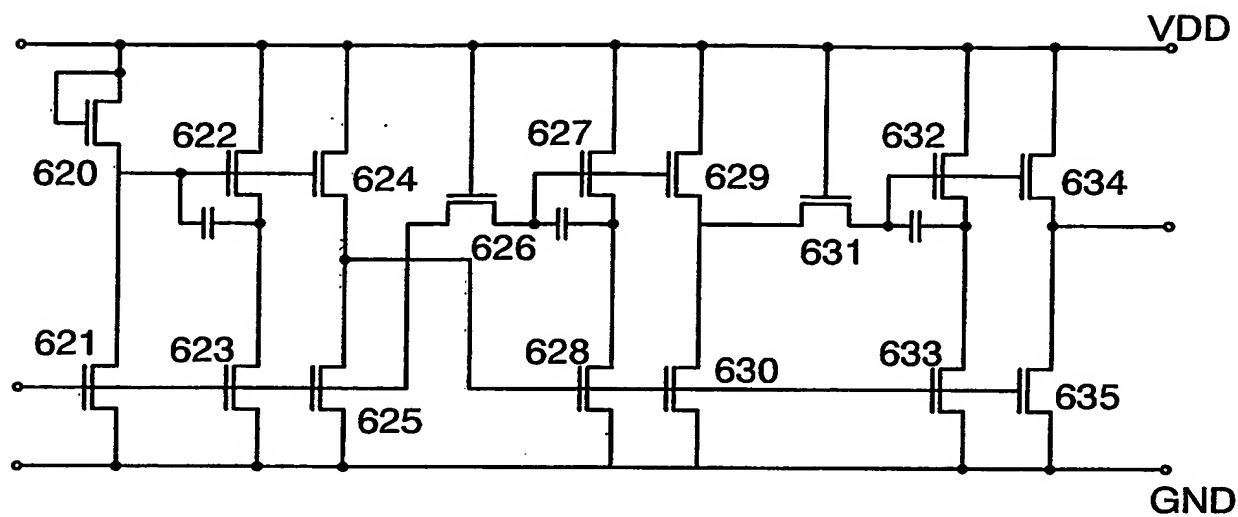


FIG. 27

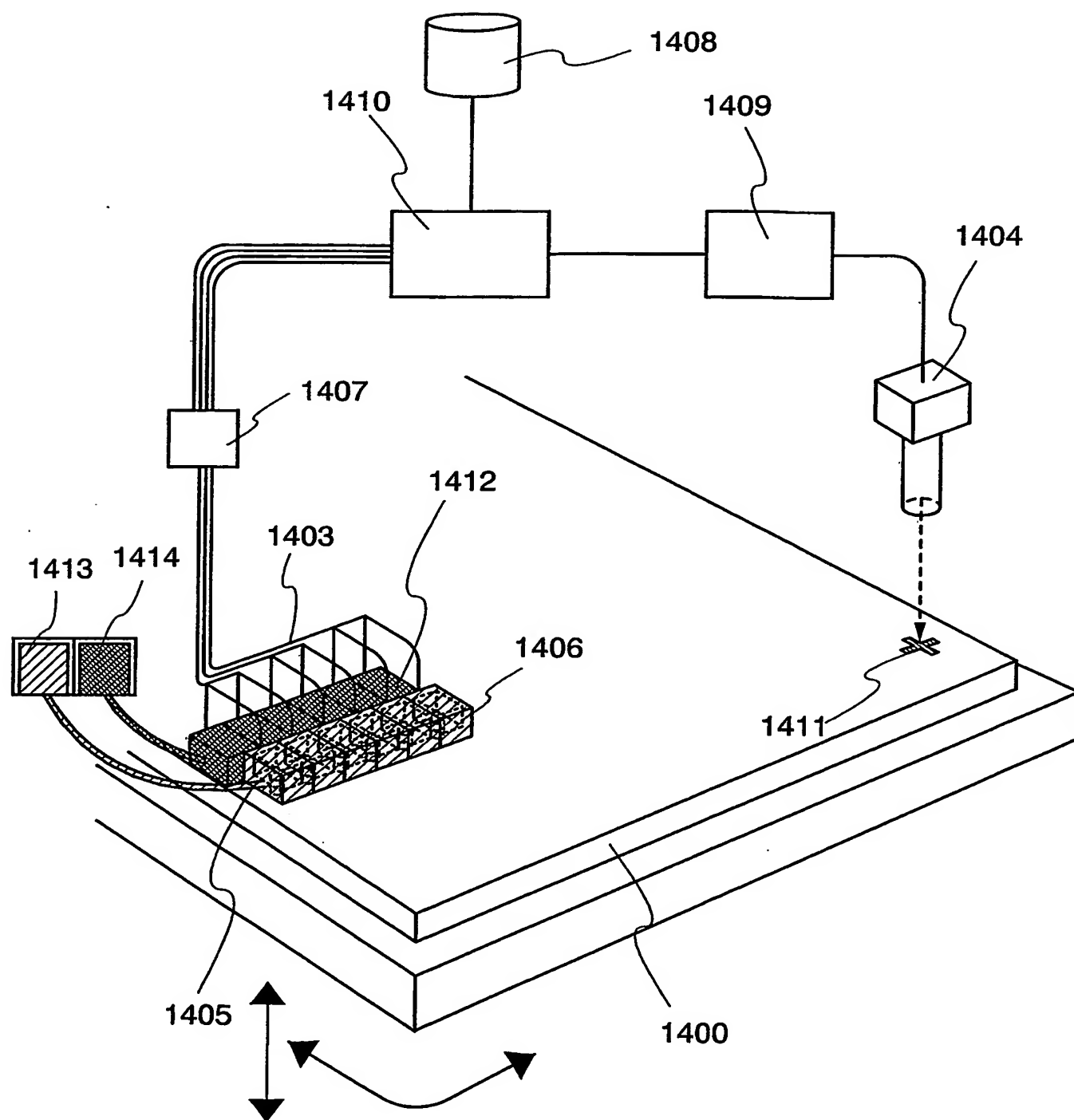


FIG. 28

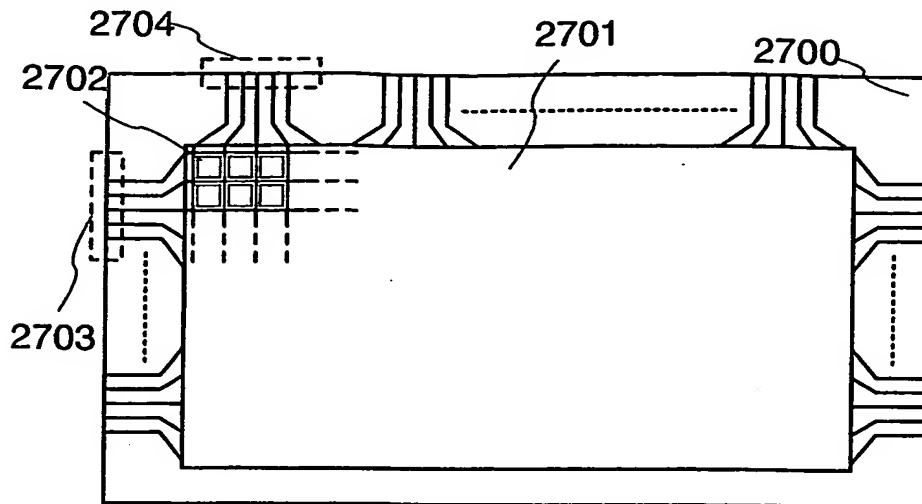


FIG. 29A

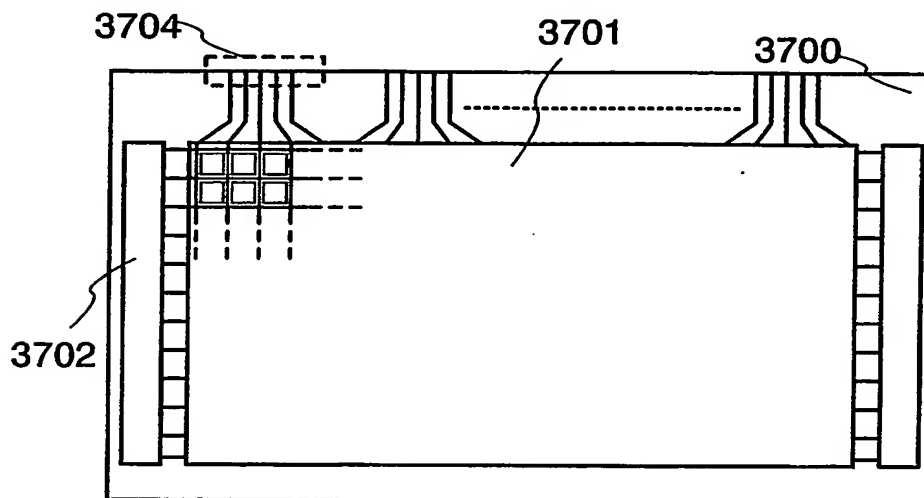


FIG. 29B

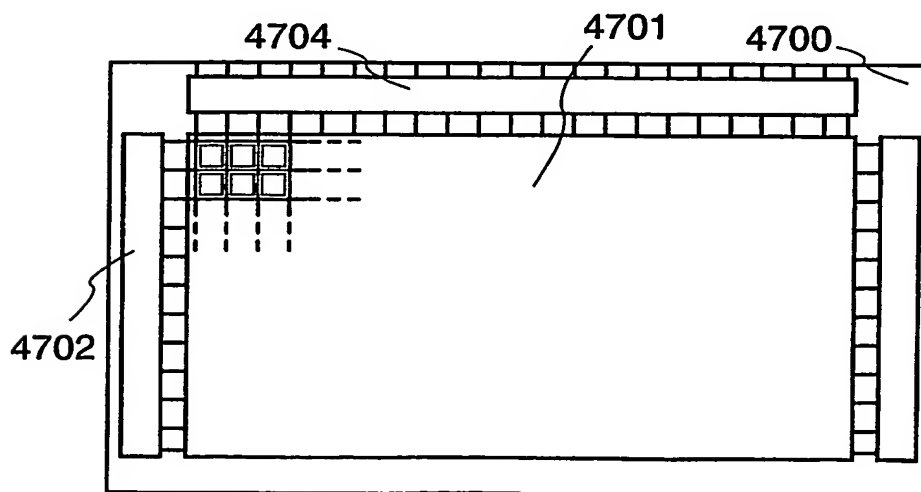


FIG. 29C

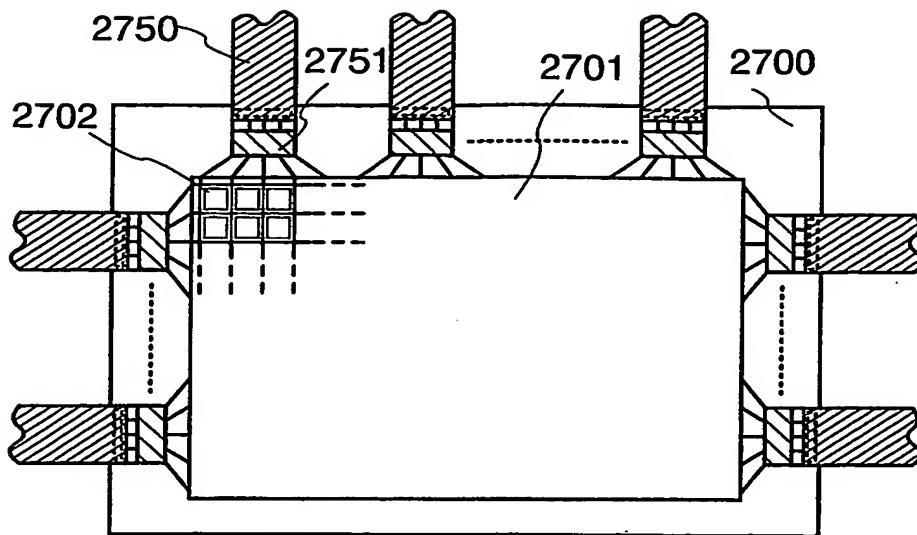


FIG. 30A

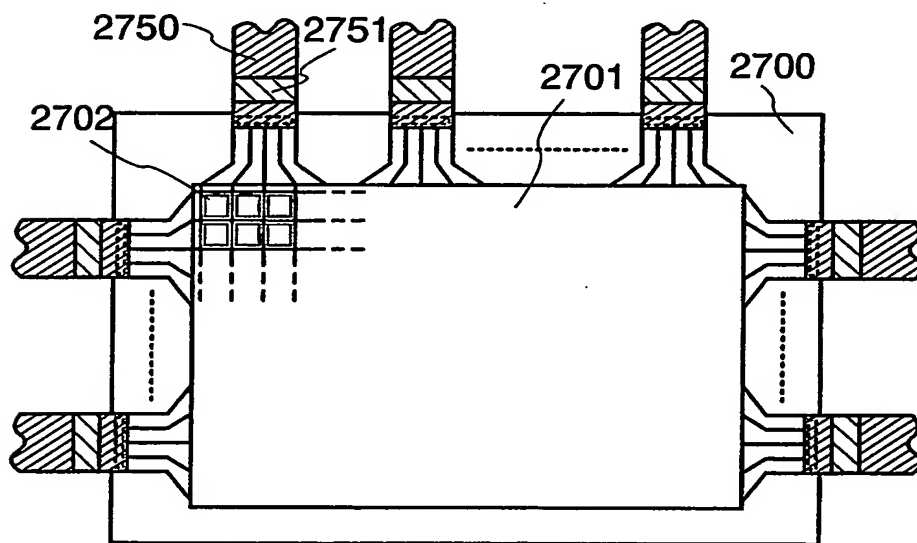


FIG. 30B

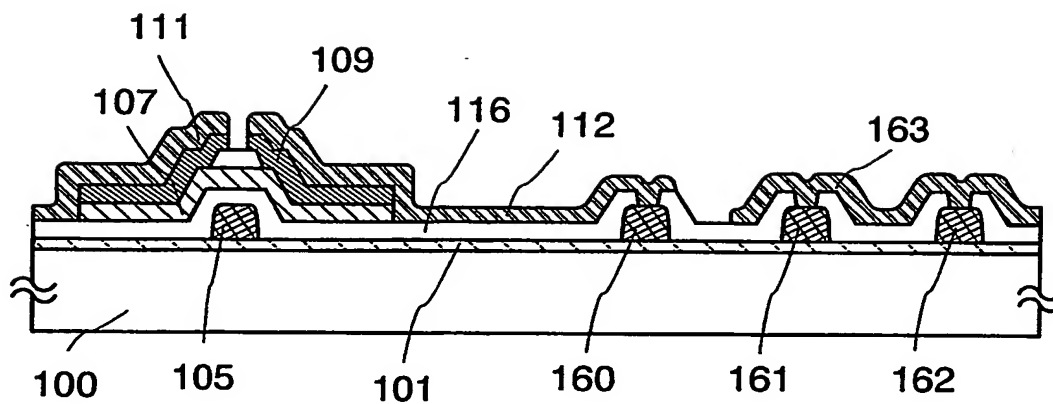


FIG. 31

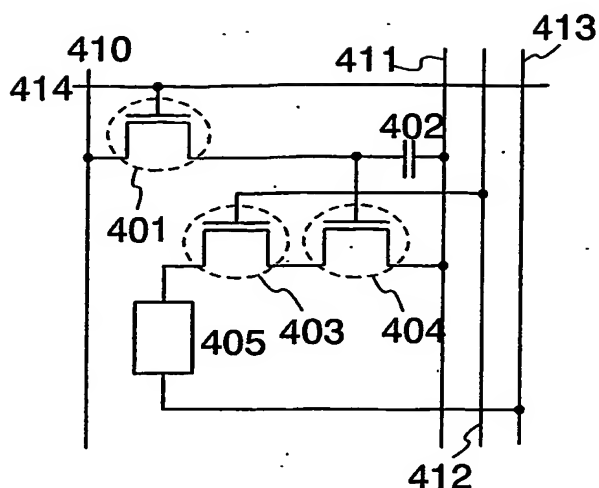


FIG. 32A

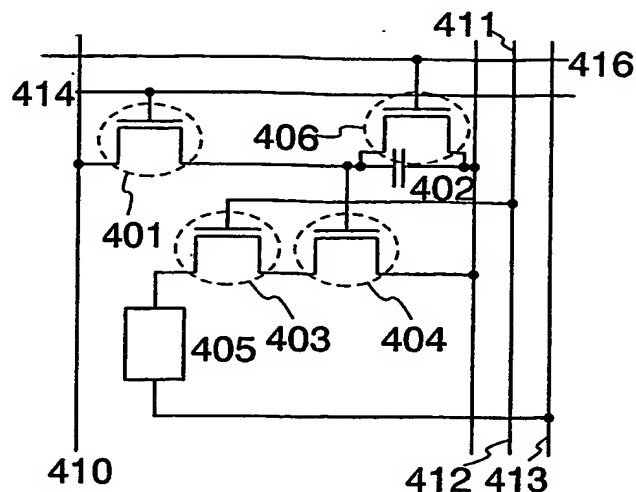


FIG. 32B

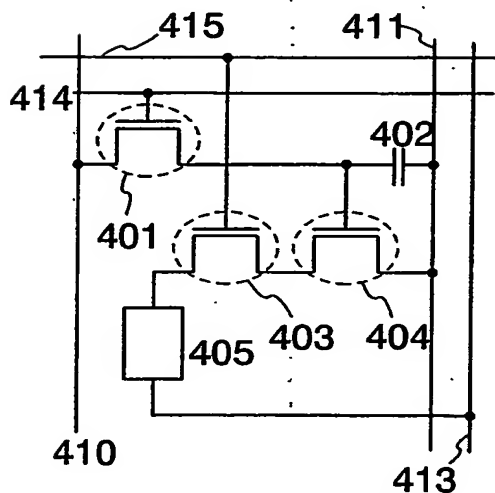


FIG. 32C

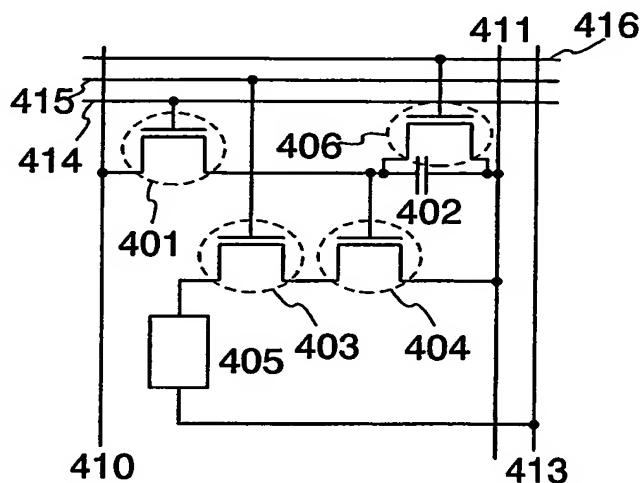


FIG. 32D

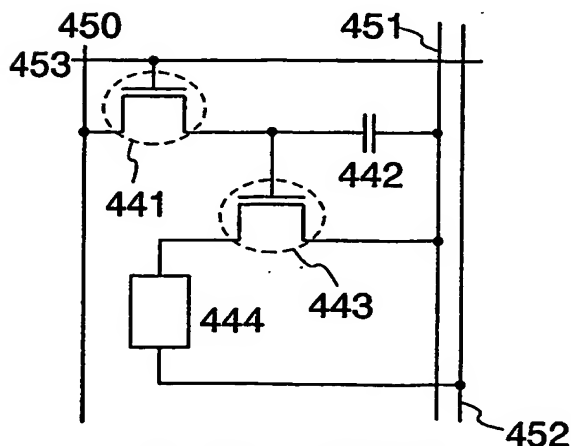


FIG. 32E

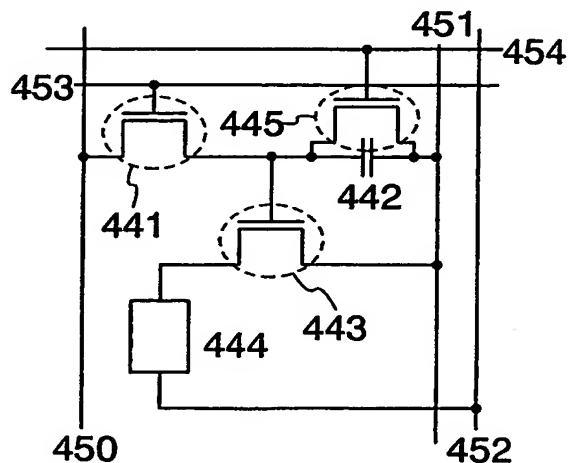


FIG. 32F

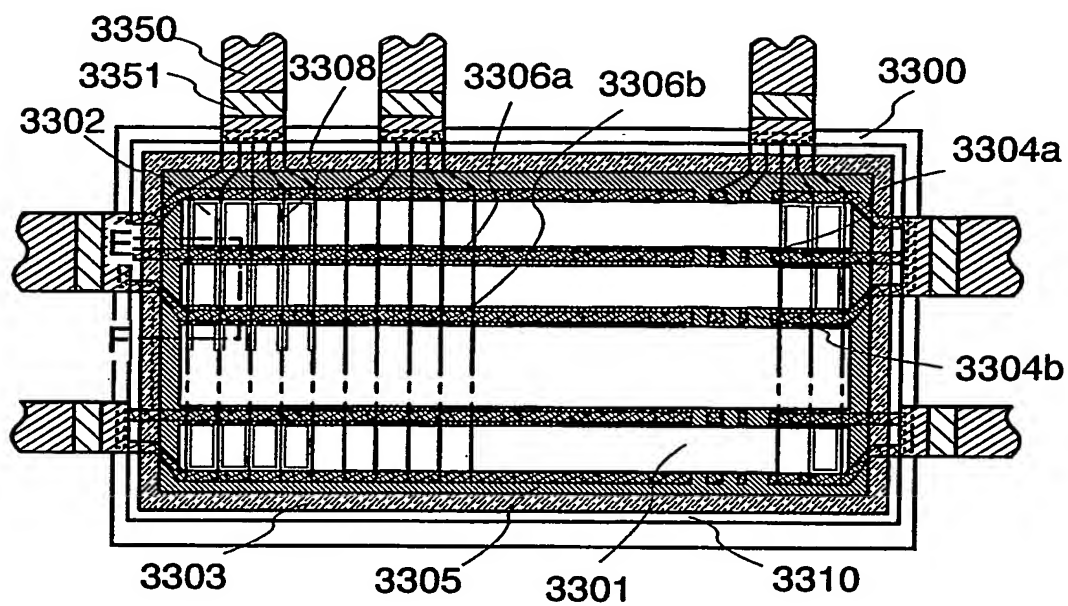


FIG. 33A

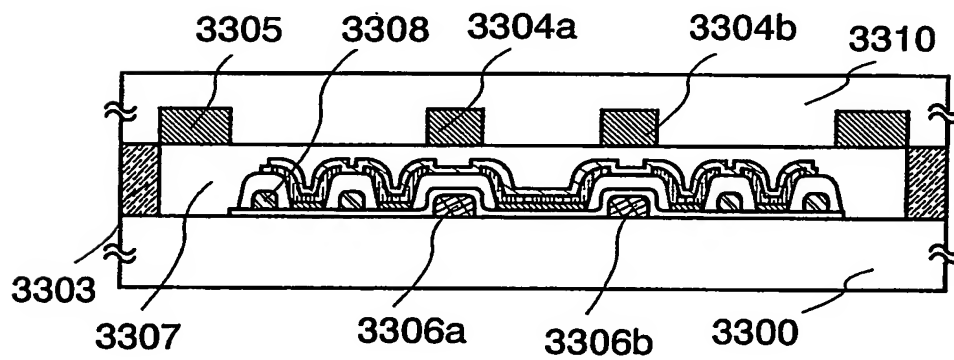


FIG. 33B

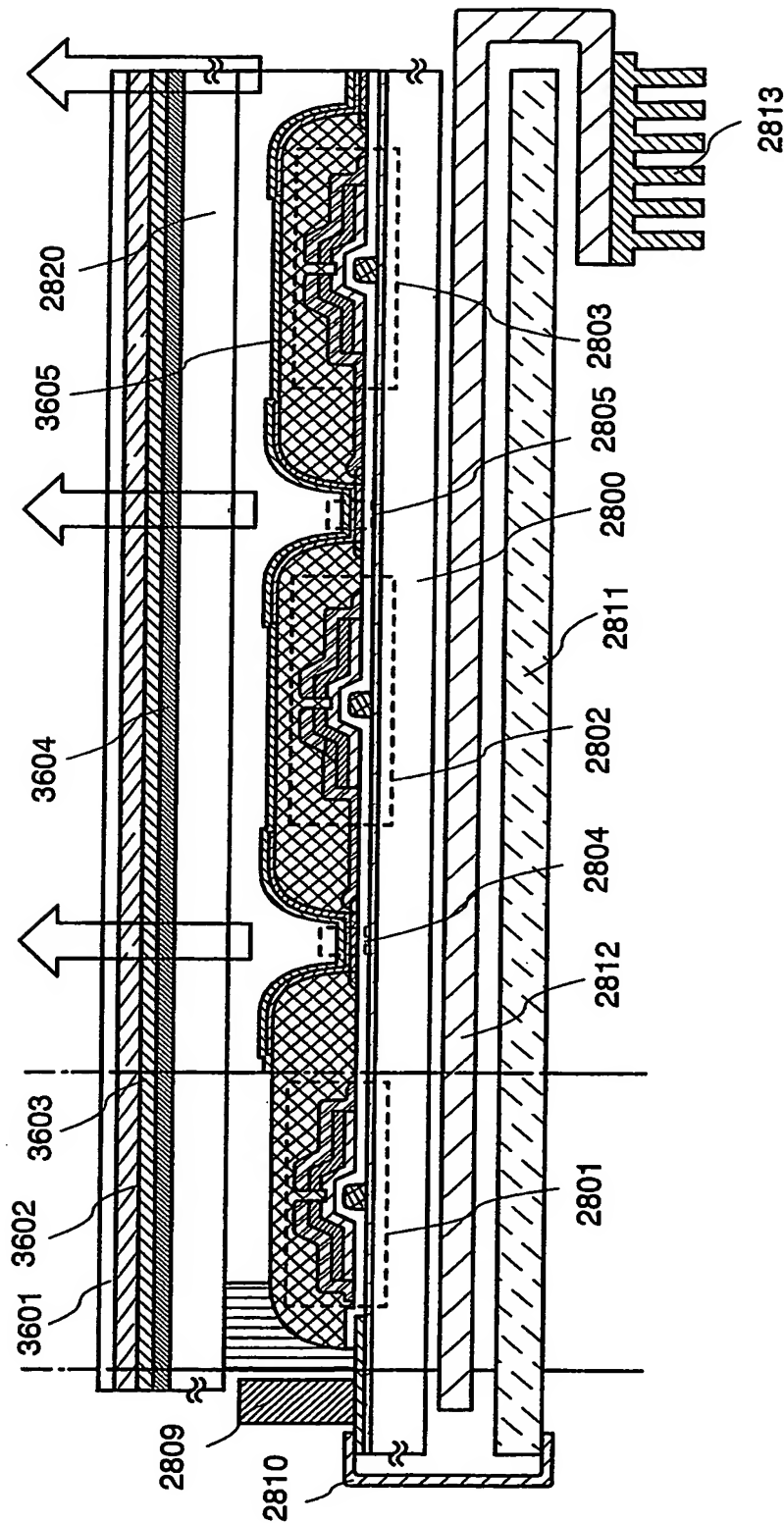


FIG. 34

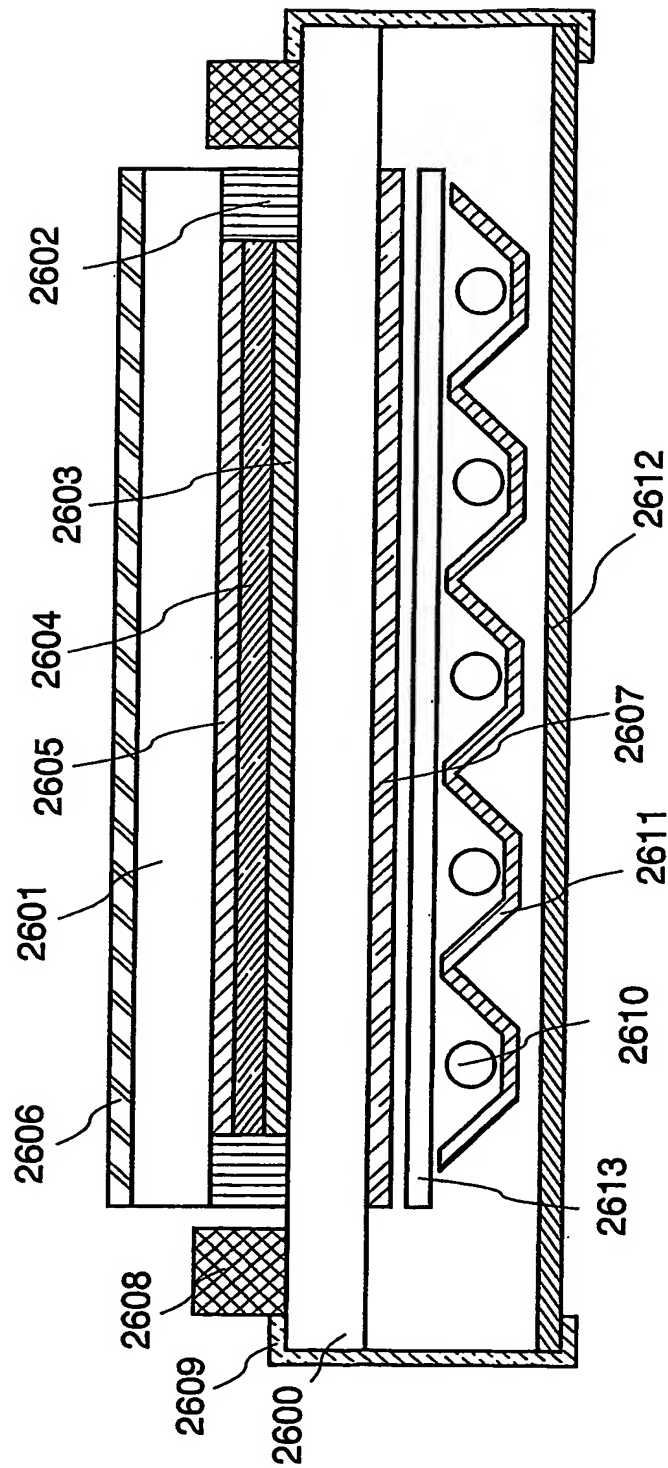


FIG. 35

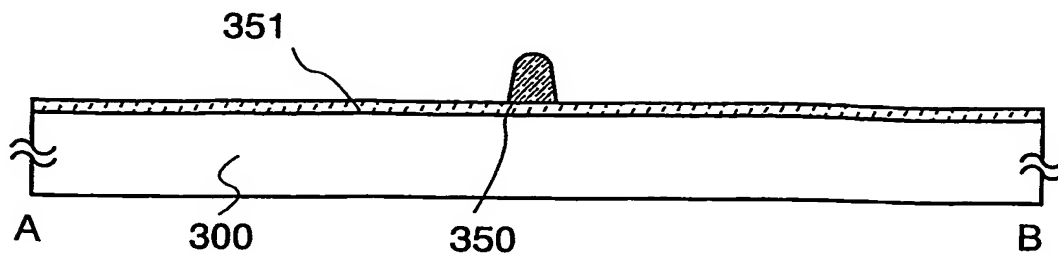


FIG. 36A

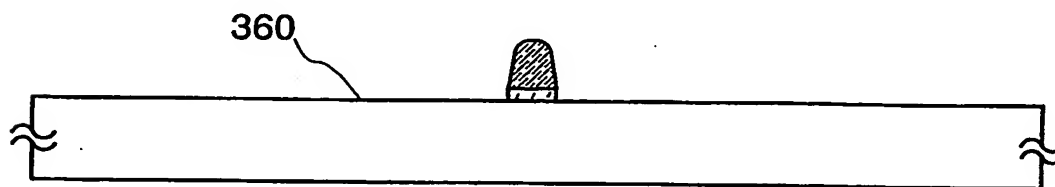


FIG. 36B

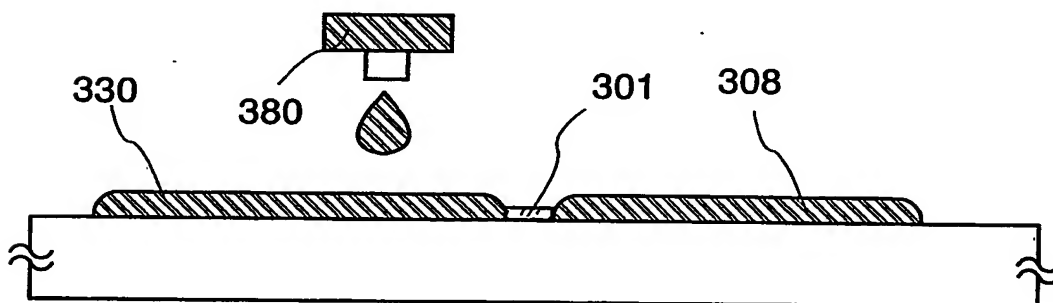


FIG. 36C

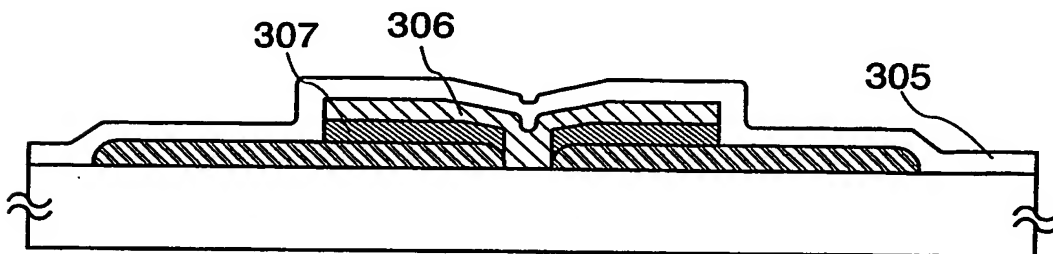


FIG. 36D

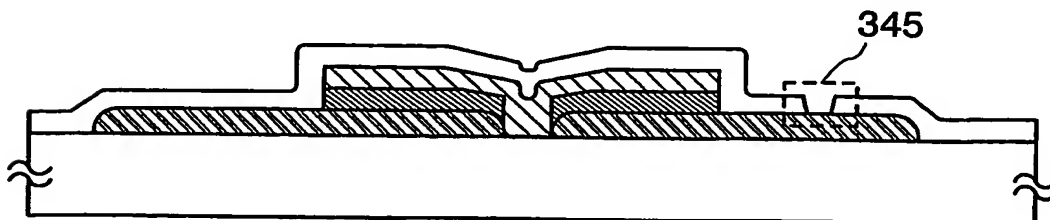


FIG. 36E

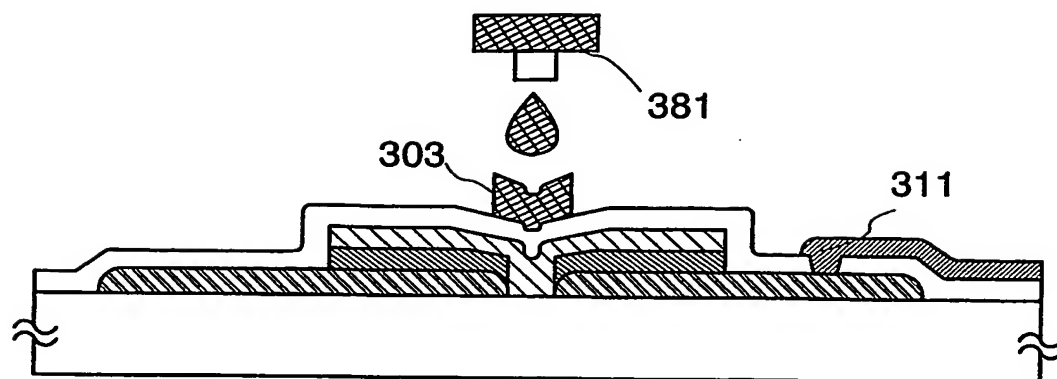


FIG. 37A

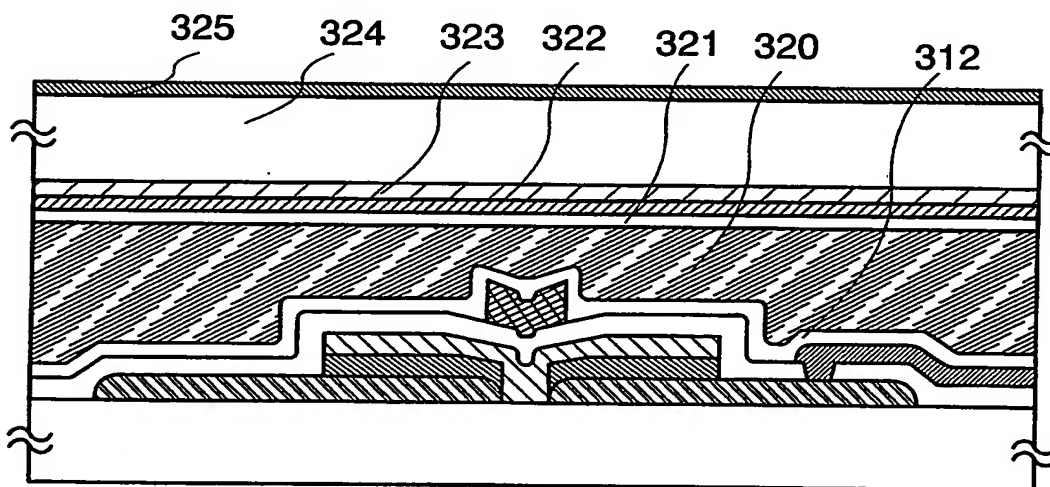


FIG. 37B

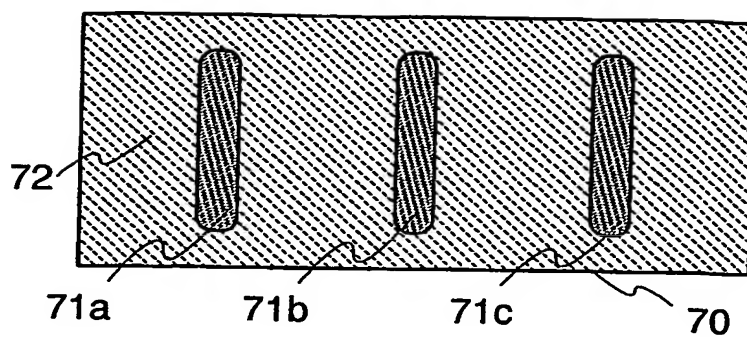


FIG. 38A

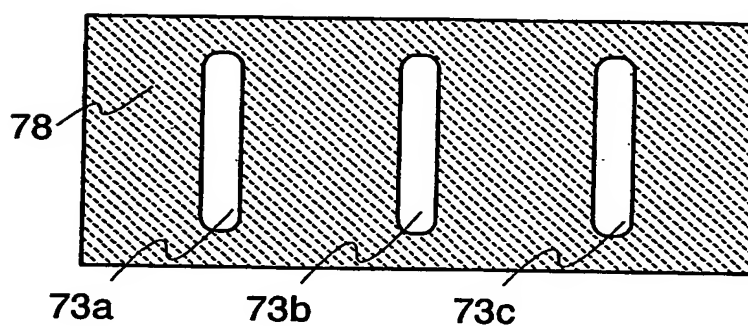


FIG. 38B

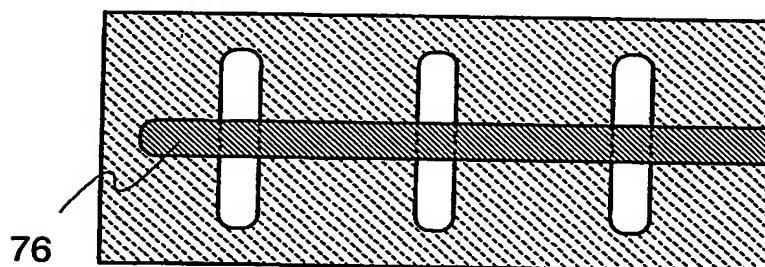


FIG. 38C

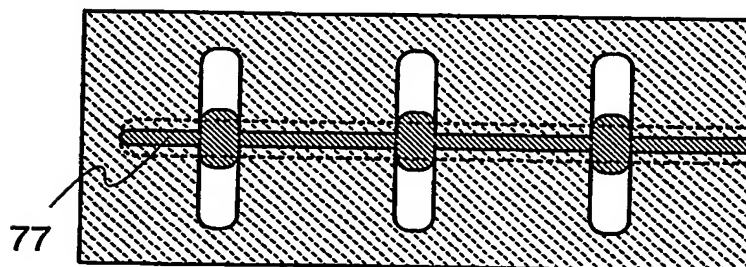


FIG. 38D

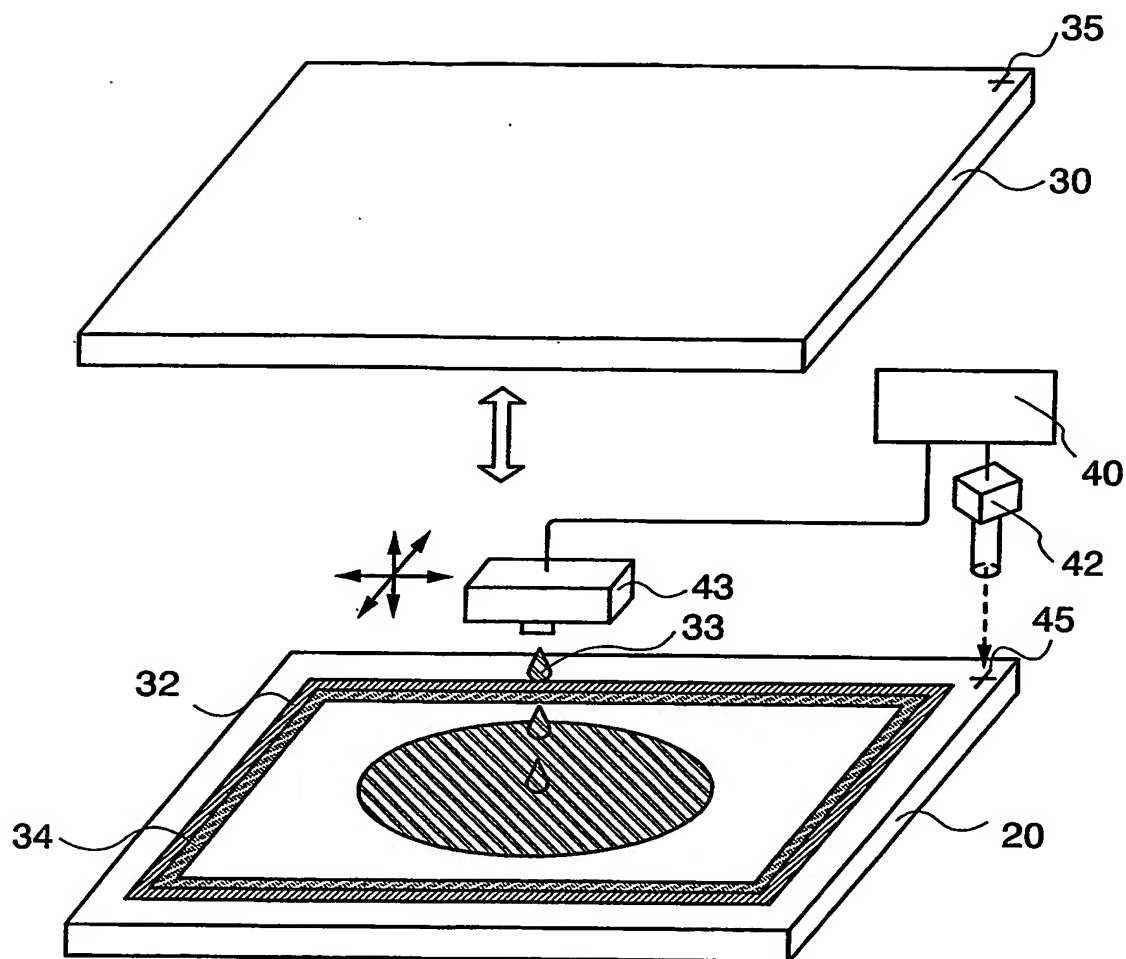


FIG. 39

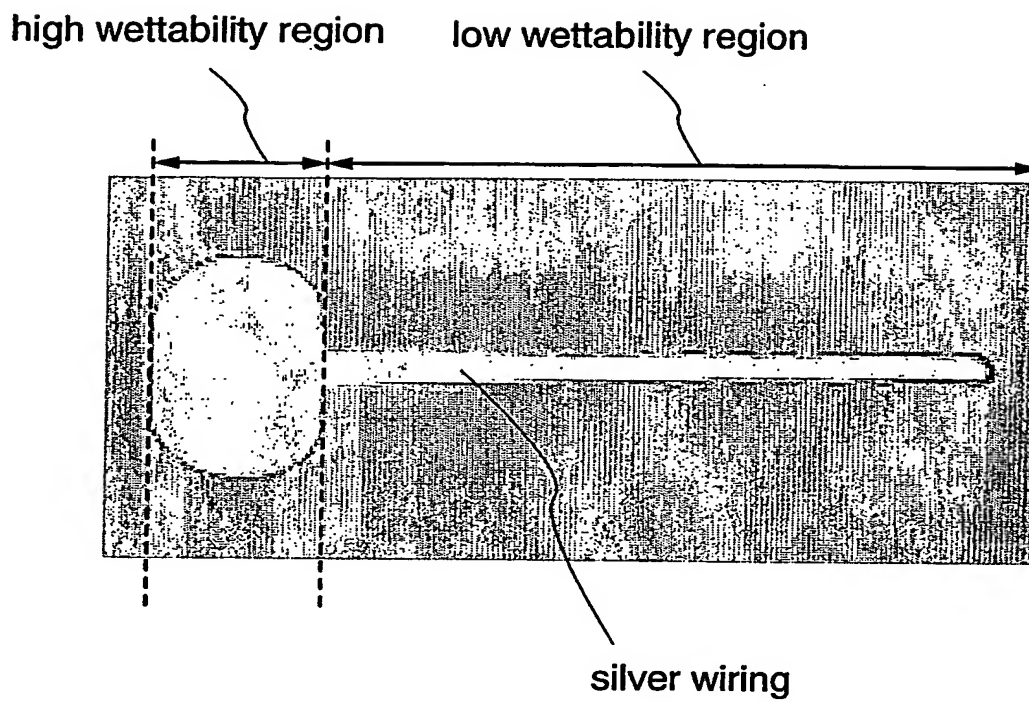


FIG. 40

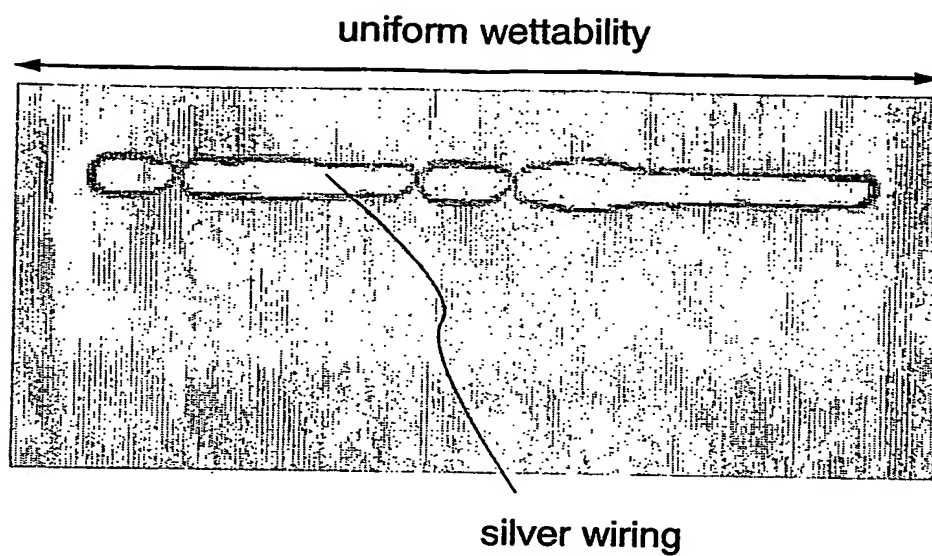


FIG. 41A

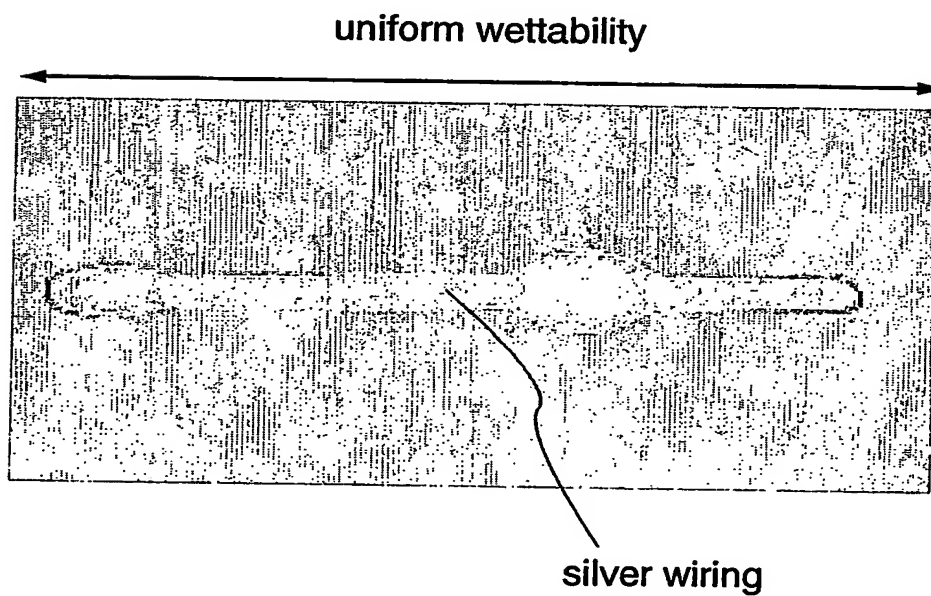


FIG. 41B

high wettability
region

low wettability region

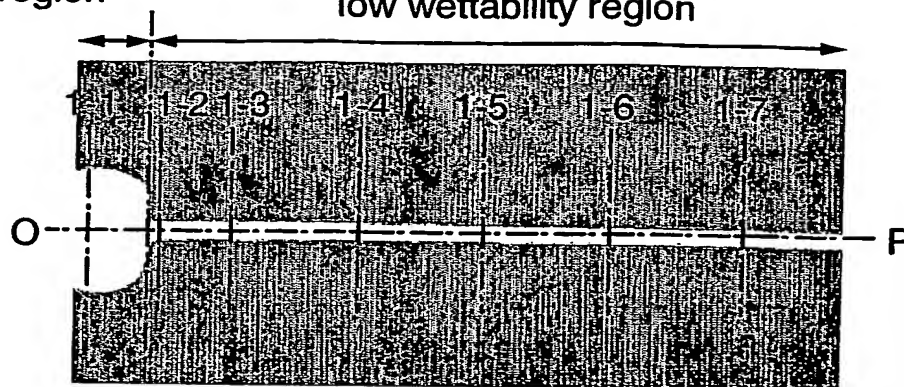


FIG. 42A



FIG. 42B

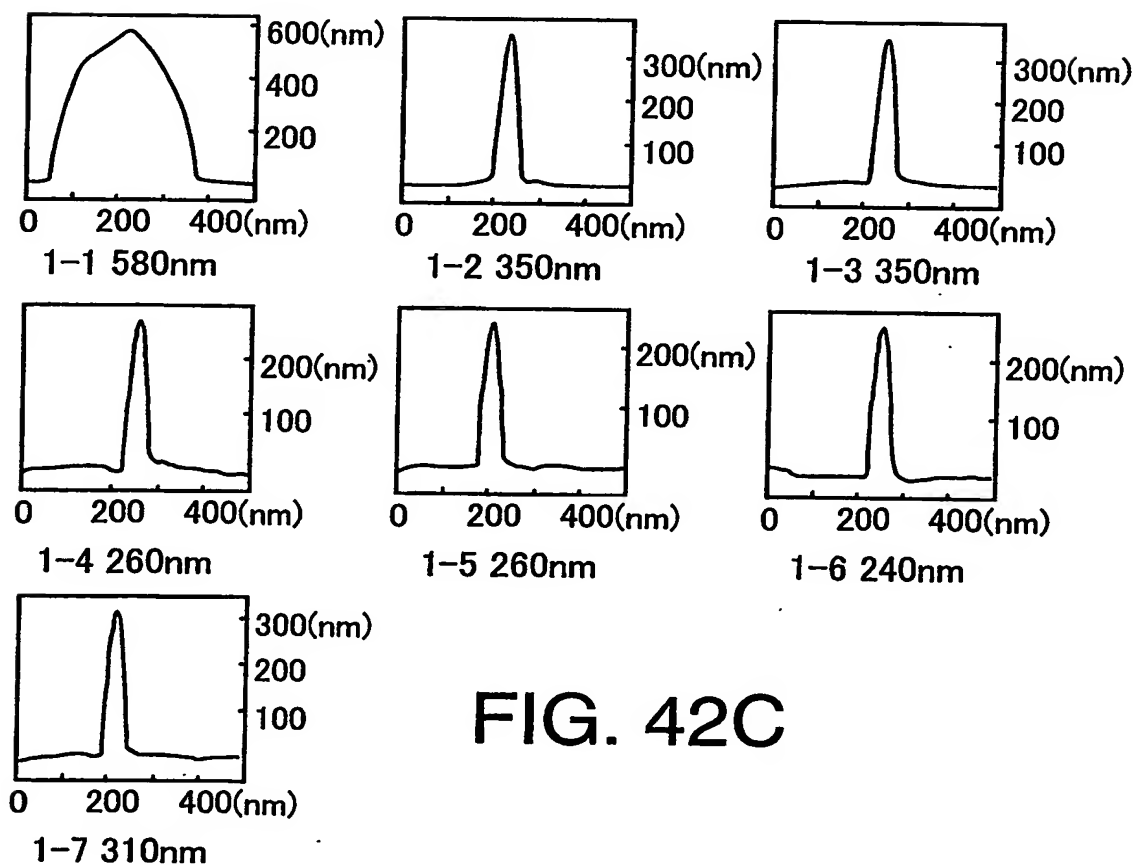


FIG. 42C

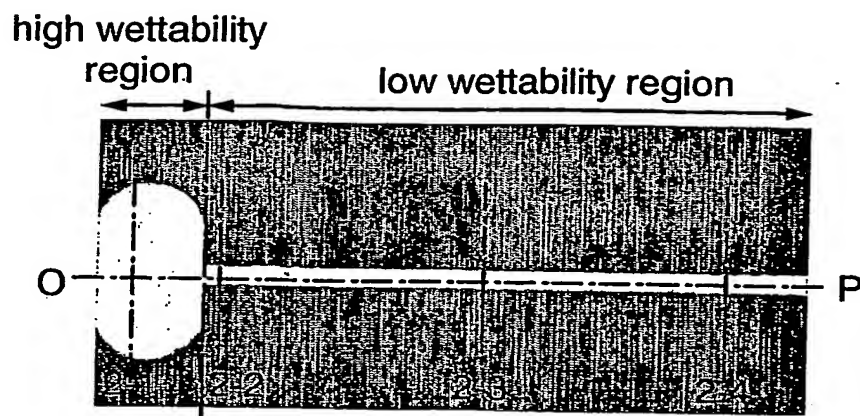


FIG. 43A

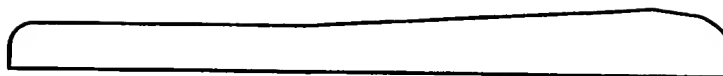


FIG. 43B

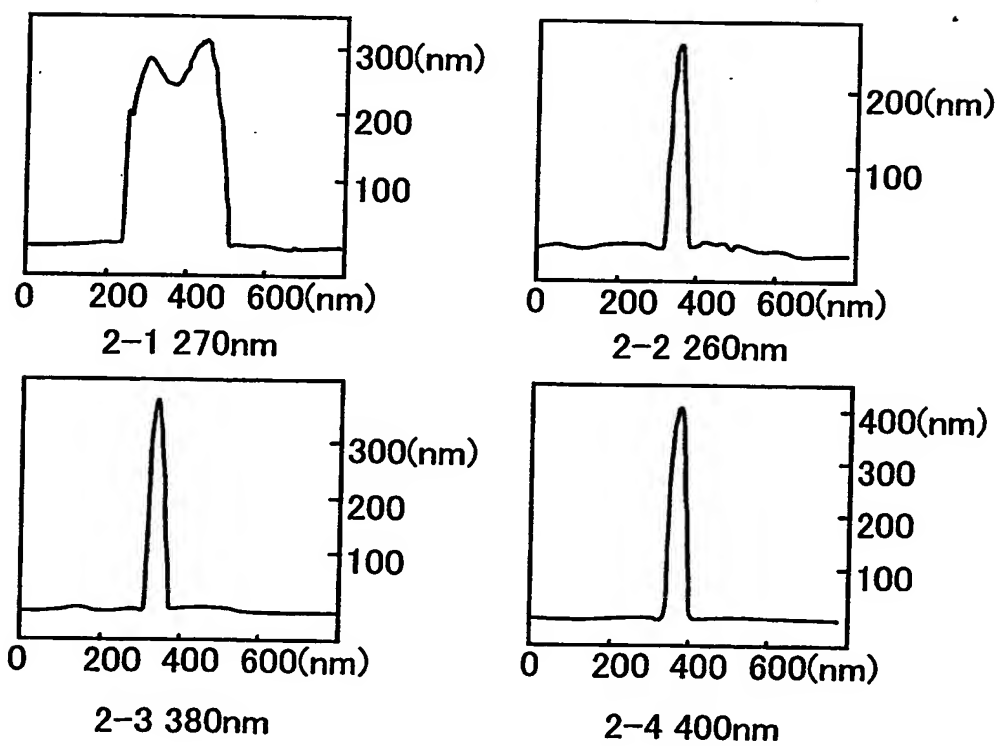


FIG. 43C

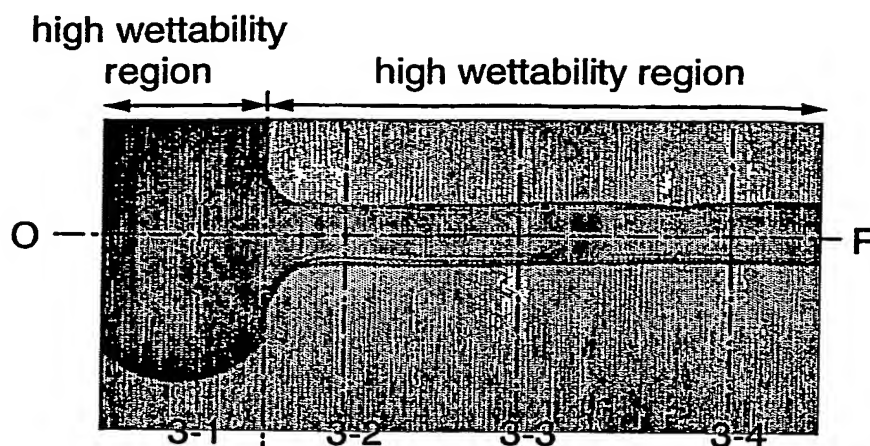


FIG. 44A



FIG. 44B

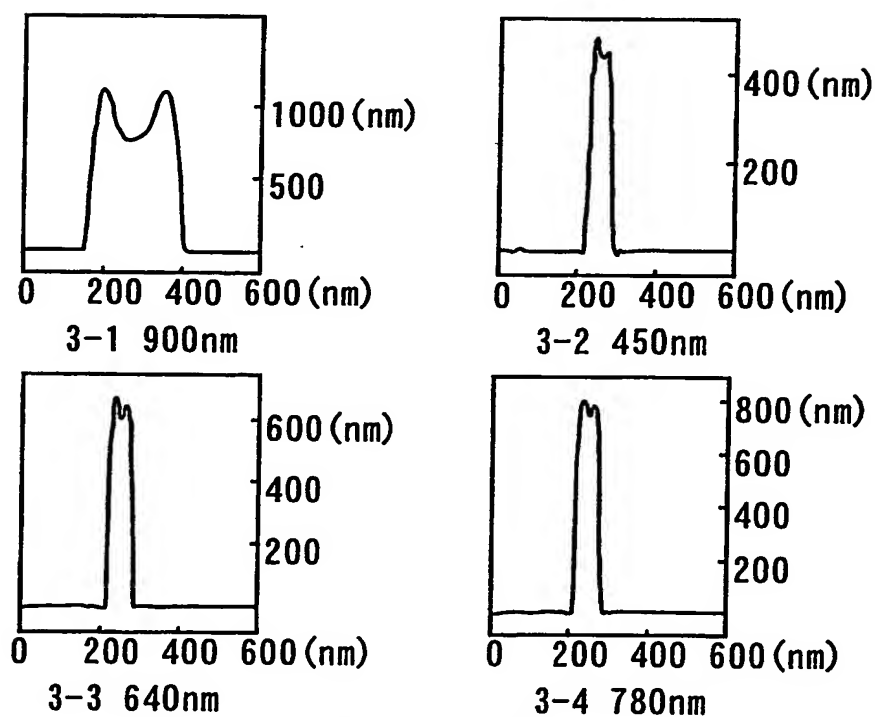


FIG. 44C

EXPLANATION OF REFERENCE

20: substrate, 30: TFT substrate, 32: sealant, 33: liquid crystal, 34: barrier layer, 35, marker, 40: control device, 42: imaging means, 43: head, 45: marker, 50: substrate, 51: mask, 52: substance, 54: nozzle, 55: droplet, 56: pattern, 57: pattern, 59: pattern, 60: nozzle, 61: droplet, 62: pattern, 63: pattern, 70: substrate, 71a: mask, 71b: mask, 71c: mask, 72: substance, 76: pattern, 77: pattern, 100: substrate, 101: mask, 103: gate electrode layer, 104: gate electrode layer, 105: gate electrode layer, 106: gate electrode layer, 107: semiconductor layer, 108: semiconductor layer, 109: n-type semiconductor layer, 110: n-type semiconductor layer, 111: drain electrode layer, 112: drain electrode layer, 113: drain electrode layer, 114: drain electrode layer, 116: gate insulating layer, 117: electrode layer, 121: insulating layer, 122: electroluminescent layer, 123: electrode layer, 125: mask, 126: high wettability region, 127: gate electrode layer, 145: contact hole, 160: connecting wiring layer, 161: connecting wiring layer, 162: connecting wiring layer, 163: connecting wiring layer, 180a: nozzle, 180b: nozzle, 301: low wettability region, 303: gate electrode layer, 305: gate insulating layer, 307: n-type semiconductor layer, 308: drain electrode layer, 311: pixel electrode layer, 312: insulating layer, 320: liquid crystal layer, 321: insulating layer, 322: colored layer, 323: conductive layer, 324: opposing substrate, 325: polarizing plate, 330: drain electrode layer, 345: contact hole, 350: pattern, 351: substance, 360: low wettability substance, 380: nozzle, 381: nozzle, 401: TFT, 402: capacitor element, 403: TFT, 404: TFT, 405: light-emitting element, 406: TFT, 410 signal line,

411: power source line, 412: power source line, 413: power source line, 414: scanning line, 415: power source line, 416: scanning line, 441: switching TFT, 442: capacitor element, 443: driver TFT, 444: light-emitting element, 445: TFT, 450: signal line, 451: power source line, 452: power source line, 453: scanning line, 454: scanning line, 462: drain electrode, 463: electrode, 464: electroluminescent layer, 465: electrode, 471: drain electrode, 472: electrode, 473: electroluminescent layer, 474: electrode, 480: substrate, 481: thin film transistor, 484: electrode, 485: electroluminescent layer, 486: electrode, 500: block, 501: TFT, 502: TFT, 503: light-emitting element, 504: capacitor element, 505: drain wiring layer, 554: common electric potential line, 555: common electric potential line, 556: common electric potential line, 557: common electric potential line, 561: protective diode, 562: protective diode, 563: protective diode, 564: protective diode, 601: TFT, 620: TFT, 901: buffer circuit, 902: pixel, 1400: substrate, 1403: droplet discharging means, 1404: imaging means, 1405: head, 1406: dotted line, 1407: controlling means, 1408: recording medium, 1409: image processing means, 1410: computer, 1411: marker, 1412: head, 1413: material supply source, 1414: material supply source, 2001: housing, 2002: display panel, 2003: main screen, 2004: modem, 2005: receiver, 2006: remote control device, 2007: display portion, 2008: sub screen, 2009: speaker portion, 2101: main body, 2102: housing, 2103: display portion, 2104: key board, 2105: external connecting port, 2106: pointing mouse, 2201: housing, 2203: display portion A, 2204: display portion B, 2206: operation key, 2207: speaker portion, 2301: main body, 2302: audio output portion, 2303: audio input portion, 2304: display

portion, 2305: operation switch, 2306: antenna, 2401: main body, 2402: display portion, 2405: remote control receiving portion, 2406: image receiving portion, 2407: battery, 2408: audio input portion, 2409: operation key, 2410: eye contact portion, 2600: TFT substrate, 2601: opposing substrate, 2602: sealant, 2603: pixel portion, 2604: liquid crystal layer, 2605: colored layer, 2606: polarizing plate, 2607: polarizing plate, 2608: driver circuit, 2609: flexible wiring substrate, 2610: cold-cathode tube, 2611: reflecting plate, 2612: circuit substrate, 2613: lens film, 2700: substrate, 2701: pixel portion, 2702: pixel, 2703: scanning line side input terminal, 2704: signal line side input terminal, 2750: FPC, 2751: driver IC, 2800: TFT substrate, 2801: protective circuit portion, 2802: TFT, 2803: TFT, 2804: light-emitting element, 2805: light-emitting element, 2806a: spacer, 2806b: spacer, 2807a: colored layer, 2807b: colored layer, 2807c: colored layer, 2809: external circuit, 2810: wiring substrate, 2811: circuit substrate, 2812: radiator plate, 2813: heat pipe, 2820: sealing substrate, 3300: device substrate, 3301: pixel portion, 3302: pixel, 3303: sealant, 3305: drying agent, 3307: filler, 3308: source wiring layer, 3310: sealing substrate, 3350: FPC, 3601: antireflection film, 3602: polarizing plate, 3603: retardation film, 3604: retardation film, 3604a: drying agent, 3604b: drying agent, 3605: insulating layer, 3306a: gate wiring layer, 3306b: gate wiring layer, 3700: substrate, 3701: pixel portion, 3702: scanning line side driver circuit, 3704: signal line side input terminal, 4700: substrate, 4701: pixel portion, 4702: scanning line driver circuit, and 4704: signal line driver circuit.

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